



#### **General Description**

The MAX1533/MAX1537 are dual step-down, switchmode power-supply (SMPS) controllers with synchronous rectification, intended for main 5V/3.3V power generation in battery-powered systems. Fixed-frequency operation with optimal interleaving minimizes input ripple current from the lowest input voltages up to the 26V maximum input. Optimal 40/60 interleaving allows the input voltage to go down to 8.3V before duty-cycle overlap occurs, compared to 180° out-of-phase regulators where the duty-cycle overlap occurs when the input drops below 10V. Output current sensing provides accurate current limit using a sense resistor. Alternatively, power dissipation can be reduced using lossless inductor current sensing.

Internal 5V and 3.3V linear regulators power the MAX1533/MAX1537 and their gate drivers, as well as external keep-alive loads, up to a total of 100mA. When the main PWM regulators are in regulation, automatic bootstrap switches bypass the internal linear regulators, providing currents up to 200mA from each linear output. An additional 5V to 23V adjustable internal 150mA linear regulator is typically used with a secondary winding to provide a 12V supply.

The MAX1533/MAX1537 include on-board power-up sequencing, a power-good (PGOOD) output, digital soft-start, and internal soft-shutdown output discharge that prevents negative voltages on shutdown. The MAX1533 is available in a 32-pin 5mm x 5mm thin QFN package, and the MAX1537 is available in a 36-pin 6mm x 6mm thin QFN package. The exposed backside pad improves thermal characteristics for demanding linear keep-alive applications.

### **Applications**

2 to 4 Li+ Cells Battery-Powered Devices Notebook and Subnotebook Computers PDAs and Mobile Communicators

### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX1533ETJ	-40°C to +85°C	32 Thin QFN 5mm x 5mm
MAX1533ETJ+	-40°C to +85°C	32 Thin QFN 5mm x 5mm
MAX1537ETX	-40°C to +85°C	36 Thin QFN 6mm x 6mm
MAX1537ETX+	-40°C to +85°C	36 Thin QFN 6mm x 6mm

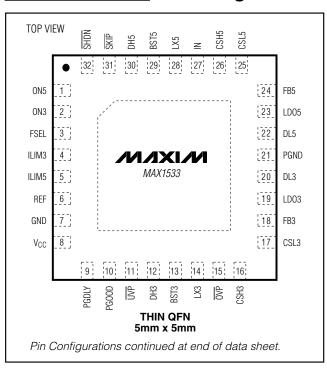
<sup>+</sup>Denotes lead-free package.

Dual Mode is a trademark of Maxim Integrated Products, Inc.

#### **Features**

- **♦** Fixed-Frequency, Current-Mode Control
- ♦ 40/60 Optimal Interleaving
- **♦** Accurate Differential Current-Sense Inputs
- ♦ Internal 5V and 3.3V Linear Regulators with 100mA Load Capability
- ♦ Auxiliary 12V or Adjustable 150mA Linear Regulator (MAX1537 Only)
- ♦ Dual-Mode™ Feedback—3.3V/5V Fixed or Adjustable Output (Dual Mode) Voltages
- ♦ 200kHz/300kHz/500kHz Switching Frequency
- **♦ Versatile Power-Up Sequencing**
- ♦ Adjustable Overvoltage and Undervoltage **Protection**
- ♦ 6V to 26V Input Range
- ♦ 2V ±0.75% Reference Output
- **♦ Power-Good Output**
- ♦ Soft-Shutdown
- ♦ 5µA (typ) Shutdown Current

### Pin Configurations



MIXIM

Maxim Integrated Products 1

#### **ABSOLUTE MAXIMUM RATINGS**

0.01/+= .001/
0.3V to +30V
0.3V to +0.3V
0.3V to +6V
0.3V to $(V_{CC} + 0.3V)$
$0.3V$ to $(V_{LDO5} + 0.3V)$
0.3V to +36V
6V to +0.3V
0.3V to $(V_{BST3} + 0.3V)$

LX5 to BST5	6V to +0.3V
DH5 to LX5	-0.3V to (V <sub>BST5</sub> + 0.3V)
LDO3, LDO5 Short Circuit to GND	Momentary
REF Short Circuit to GND	Momentary
INA Shunt Current	+15mÅ
Continuous Power Dissipation (T <sub>A</sub> = +70°	
32-Pin TQFN (derate 21.3mW/°C abov	re +70°C)1702mW
36-Pin TQFN (derate 26.3mW/°C abov	re +70°C)2105mW
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  = 12V,  $V_{LDO5}$  = 1

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
INPUT SUPPLIES (Note 1)						•
V. Janut Valtaga Danga	V	LDO5 in regulation	6		26	V
V <sub>IN</sub> Input Voltage Range	V <sub>IN</sub>	IN = LDO5, V <sub>OUT5</sub> < 4.43V	4.5		5.5	]
V <sub>IN</sub> Operating Supply Current	I <sub>IN</sub>	LDO5 switched over to CSL5		15	35	μΑ
V <sub>IN</sub> Standby Supply Current	I <sub>IN(STBY)</sub>	$V_{IN} = 6V$ to 26V, both SMPS off, includes $\overline{I_{SHDN}}$		100	170	μΑ
V <sub>IN</sub> Shutdown Supply Current	In(shdn)	V <sub>IN</sub> = 6V to 26V, SHDN = GND		5	17	μΑ
Quiescent Power Consumption	PQ	Both SMPS on, FB3 = FB5 = SKIP = GND, VCSL3 = 3.5V, VCSL5 = 5.3V, VINA = 15V, ILDOA = 0, PIN + PCSL3 + PCSL5 + PINA		3.5	4.5	mW
V <sub>CC</sub> Quiescent Supply Current	Icc	Both SMPS on, FB3 = FB5 = GND, V <sub>CSL3</sub> = 3.5V, V <sub>CSL5</sub> = 5.3V		1.1	2.1	mA
MAIN SMPS CONTROLLERS						
3.3V Output Voltage in Fixed Mode	V <sub>OUT3</sub>	$V_{IN} = 6V$ to 26V, $\overline{SKIP} = V_{CC}$ (Note 2)	3.280	3.33	3.380	V
5V Output Voltage in Fixed Mode	V <sub>OUT5</sub>	V <sub>IN</sub> = 6V to 26V, SKIP = V <sub>CC</sub> (Note 2)	4.975	5.05	5.125	V
Feedback Voltage in Adjustable Mode	V <sub>FB</sub> _	V <sub>IN</sub> = 6V to 26V, FB3 or FB5, duty factor = 20% to 80% (Note 2)	0.990	1.005	1.020	V
Output-Voltage Adjust Range		Either SMPS	1.0		5.5	V
FB3, FB5 Dual-Mode Threshold			0.1		0.2	V
Feedback Input Leakage Current		V <sub>FB3</sub> = V <sub>FB5</sub> = 1.1V	-0.1		+0.1	μΑ
DC Load Regulation		Either SMPS, SKIP = V <sub>CC</sub> , I <sub>LOAD</sub> = 0 to full load		-0.1		%

### **ELECTRICAL CHARACTERISTICS (continued)**

(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  = 12V,  $V_{LDO5}$  = 1

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Line-Regulation Error		Either SMPS, duty	/ cycle = 10% to 90%		1		%
		FSEL = GND		170	200	230	
Operating Frequency (Note 1)	fosc	FSEL = REF		270	300	330	kHz
		FSEL = V <sub>CC</sub>		425	500	575	
		FSEL = GND		91	93		
Maximum Duty Factor (Note 1)	D <sub>MAX</sub>	FSEL = REF		91	93		%
		FSEL = V <sub>CC</sub>		91	93		
Minimum On-Time	ton(MIN)	(Note 3)				200	ns
SMPS3 to SMPS5 Phase Shift		SMPS5 starts afte	er SMPS3		40		%
		Olvii Go diarto arte	N GIVII GO		144		Deg
CURRENT LIMIT	1						,
ILIM_ Adjustment Range				0.5		V <sub>REF</sub>	V
Current-Sense Input Range		CSH_, CSL_		0		5.5	V
Current-Sense Input Leakage Current		CSH_, V <sub>CSH</sub> _ = 5	.5V	-1		+1	μΑ
Current-Limit Threshold (Fixed)	V <sub>LIMIT</sub> _	V <sub>CSH</sub> V <sub>CSL</sub> _, IL	-IM_ = VCC	70	75	80	mV
	V <sub>LIMIT</sub> _	VCSH VCSL_	V <sub>ILIM</sub> _ = 2.00V	170	200	230	mV
Current-Limit Threshold (Adjustable)			$V_{ILIM} = 1.00V$	91	100	109	
(Adjustable)			$V_{ILIM} = 0.50V$	42	50	58	
Current-Limit Threshold (Negative)	VNEG	V <sub>CSH</sub> V <sub>CSL</sub> _, Si current limit	$\overline{XIP} = V_{CC}$ , percent of		-120		%
Current-Limit Threshold (Zero Crossing)	V <sub>Z</sub> X	V <sub>PGND</sub> - V <sub>LX</sub> , SK	IP = GND, ILIM_ = V <sub>CC</sub>		3		mV
			ILIM_ = VCC	10	16	22	mV
Idle-Mode™ Threshold	VIDLE	VCSH VCSL_	With respect to current- limit threshold (V <sub>LIMIT</sub> )		20		%
ILIM_ Leakage Current		ILIM3 = ILIM5 = 0	GND or V <sub>CC</sub>	-0.1		+0.1	μΑ
Soft-Start Ramp Time	tss	Measured from the	e rising edge of ON_ to		512 / fosc		S
INTERNAL FIXED LINEAR REGUI	ATORS	•					
LDO5 Output Voltage	V <sub>LDO5</sub>	ON3 = ON5 = GND, 6V < V <sub>IN</sub> < 26V, 0 < I <sub>LDO5</sub> < 100mA		4.80	4.95	5.10	V
LDO5 Undervoltage-Lockout Fault Threshold		Rising edge, hysteresis = 1%		3.75	4.0	4.25	V
LDO5 Bootstrap Switch Threshold		Rising edge of CS	SL5, hysteresis = 1%	4.41		4.75	V
LDO5 Bootstrap Switch Resistance		LDO5 to CSL5, Vo	CSL5 = 5V,		0.75	3	Ω

Idle Mode is a trademark of Maxim Integrated Products, Inc.



### **ELECTRICAL CHARACTERISTICS (continued)**

(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  $V_{LDO5}$  =

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
LDO3 Output Voltage	V <sub>LDO3</sub>	Standby mode, 6V < V <sub>IN</sub> < 26V, 0 < I <sub>LOAD</sub> < 100mA	3.20	3.35	3.42	V
LDO3 Bootstrap Switch Threshold		Rising edge of CSL3, hysteresis = 1%	2.83		3.10	V
LDO3 Bootstrap Switch Resistance		LDO3 to CSL3, V <sub>CSL3</sub> = 3.2V, I <sub>LDO3</sub> = 50mA		1	3	Ω
Short-Circuit Current		LDO3 = LDO5 = GND, CSL3 = CSL5 = GND		150	220	mA
Short-Circuit Current (Switched Over to CSL_)		LDO3 = LDO5 = GND, V <sub>CSL3</sub> > 3.1V, V <sub>CSL5</sub> > 4.7V	250			mA
AUXILIARY LINEAR REGULATOR	R (MAX1537 C	DNLY)	•			<u> </u>
LDOA Voltage Range	V <sub>LDOA</sub>		5		23	V
INA Voltage Range	VINA		6		24	V
LDOA Regulation Threshold, Internal Feedback		ADJA = GND, 0 < I <sub>LDOA</sub> < 120mA, V <sub>INA</sub> > 13V	11.4	12.0	12.4	V
ADJA Regulation Threshold, External Feedback	V <sub>ADJA</sub>	0 < I <sub>LDOA</sub> < 120mA, V <sub>LDOA</sub> > 5.0V and V <sub>INA</sub> > V <sub>LDOA</sub> + 1V	1.94	2.00	2.06	V
ADJA Dual-Mode Threshold			0.1	0.15	0.2	V
ADJA Leakage Current		$V_{ADJA} = 2.1V$	-0.1		+0.1	μΑ
LDOA Current Limit		V <sub>LDOA</sub> forced to V <sub>INA</sub> - 1V, V <sub>ADJA</sub> = 1.9V, V <sub>INA</sub> > 6V	150			mA
Secondary Feedback Regulation Threshold		V <sub>INA</sub> - V <sub>LDOA</sub>	0.65	0.8	0.95	V
DL Duty Factor		V <sub>INA</sub> - V <sub>LDOA</sub> < 0.7V, pulse width with respect to switching period		33		%
INA Quiescent Current	I <sub>INA</sub>	V <sub>INA</sub> = 24V, I <sub>LDOA</sub> = no load		50	165	μΑ
INA Shunt Sink Current		V <sub>INA</sub> = 28V	10			mA
INA Leakage Current	Ina(shdn)	V <sub>INA</sub> = 5V, LDOA disabled			30	μΑ
REFERENCE (REF)						
Reference Voltage	$V_{REF}$	$V_{CC} = 4.5V \text{ to } 5.5V, I_{REF} = 0$	1.985	2.00	2.015	V
Reference Load Regulation		$I_{REF} = -10\mu A \text{ to } +100\mu A$	1.980		2.020	V
REF Lockout Voltage	VREF(UVLO)	Rising edge, hysteresis = 350mV		1.95		V
FAULT DETECTION	T		Т			
Output Overvoltage Trip Threshold		OVP = GND, with respect to error- comparator threshold	8	11	15	%
Output Overvoltage Fault- Propagation Delay	tovp	50mV overdrive		10		μs

### **ELECTRICAL CHARACTERISTICS (continued)**

(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  $V_{LDO5}$  =

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS		
Output Undervoltage-Protection Trip Threshold		With respect to error-compara	tor threshold	65	70	75	%	
Output Undervoltage Fault- Propagation Delay	tuvp	50mV overdrive			10		μs	
Output Undervoltage-Protection Blanking Time	tBLANK	From rising edge of ON_			6144 / fosc		S	
PGOOD Lower Trip Threshold		With respect to error-compara threshold, hysteresis = 1%	tor	-14	-10	-7.5	%	
PGOOD Propagation Delay	tpgood_	Falling edge, 50mV overdrive			10		μs	
PGOOD Output Low Voltage		I <sub>SINK</sub> = 4mA				0.4	V	
PGOOD Leakage Current	IPGOOD_	High state, PGOOD forced to	5.5V			1	μΑ	
PGDLY Pullup Current		PGDLY = GND		4	5	6	μΑ	
PGDLY Pulldown Resistance					10	25	Ω	
PGDLY Trip Threshold				REF- 0.2	REF	REF+ 0.2	V	
Thermal-Shutdown Threshold	T <sub>SHDN</sub>	Hysteresis = 15°C			+160		°C	
GATE DRIVERS	•							
DH_ Gate-Driver On-Resistance	R <sub>DH</sub>	BST LX_ forced to 5V			1.5	5	Ω	
	İ	DL_, high state		1.7	5	_		
DL_ Gate-Driver On-Resistance	R <sub>DL</sub>	DL_, low state			0.6	3	Ω	
DH_ Gate-Driver Source/Sink Current	I <sub>DH</sub>	DH_ forced to 2.5V, BST LX_ forced to 5V			2		А	
DL_ Gate-Driver Source Current	I <sub>DL</sub>	DL_ forced to 2.5V			1.7		А	
DL_ Gate-Driver Sink Current	IDL (SINK)	DL_ forced to 2.5V			3.3		А	
	== (=,	DL_ rising			35			
Dead Time	tDEAD	DH_ rising			26		ns	
LX_, BST_ Leakage Current		V <sub>BST</sub> _ = V <sub>L</sub> X_ = 26V			<2	20	μΑ	
INPUTS AND OUTPUTS	1	,		ı				
			High	2.4				
Logic Input Voltage		SKIP, hysteresis = 600mV	Low			0.8	V	
Fault Enable Logic Input Voltage		OVP, UVP, ONA	High	0.7 x V <sub>CC</sub>			V	
		Low				0.4		
Logic Input Current		OVP, UVP, SKIP, ONA		-1		+1	μΑ	
CLIDN Input Trip I avail		Rising trip level		1.10	1.6	2.20	V	
SHDN Input Trip Level		Falling trip level		0.96	1	1.04	V	
		Clear fault level/SMPS off level				0.8		
ON_ Input Voltage		Delay start level (REF)		1.9		2.1	\ \ \ \	
ON_ input voltage		SMPS on level		_			· ·	



### **ELECTRICAL CHARACTERISTICS (continued)**

(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  =  $V_{LDO5}$  = 12V,  $V_{LDO5}$  = 1

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
		High	V <sub>CC</sub> - 0.2			
FSEL Three-Level Input Logic		REF	1.7		2.3	V
		GND			0.4	
Input Looks on Current		OVP, UVP, SKIP, ONA, ON3, ON5 = GND or VCC	-1		+1	
Input Leakage Current		SHDN, 0V or 26V	-1		+1	μΑ
		FSEL = GND or V <sub>CC</sub>	-3		+3	
CSL_ Discharge-Mode On-Resistance	RDISCHARGE			10	25	Ω
CSL_ Synchronous-Rectifier Discharge-Mode Turn-On Level			0.2	0.3	0.4	V

#### **ELECTRICAL CHARACTERISTICS**

(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  $V_{LDO5}$  =

PARAMETER	PARAMETER SYMBOL CO		MIN	MAX	UNITS
INPUT SUPPLIES (Note 1)					•
Var Input Voltage Denge	\/	LDO5 in regulation	6	26	V
V <sub>IN</sub> Input Voltage Range	VIN	IN = LDO5, V <sub>OUT5</sub> < 4.4V	4.5	5.5	V
V <sub>IN</sub> Operating Supply Current	I <sub>IN</sub>	LDO5 switched over to CSL5, either SMPS on		35	μΑ
V <sub>IN</sub> Standby Supply Current	I <sub>IN</sub> (STBY)	V <sub>IN</sub> = 6V to 26V, both SMPS off, includes ISHDN		170	μΑ
V <sub>IN</sub> Shutdown Supply Current	I <sub>IN</sub> (SHDN)	V <sub>IN</sub> = 6V to 26V		17	μΑ
Quiescent Power Consumption	PQ	Both SMPS on, FB3 = FB5 = SKIP = GND, VCSL3 = 3.5V, VCSL5 = 5.3V, VINA = 15V, ILDOA = 0, PIN + PCSL3 + PCSL5 + PINA		4.5	mW
V <sub>CC</sub> Quiescent Supply Current	Icc	Both SMPS on, FB3 = FB5 = GND, V <sub>CSL3</sub> = 3.5V, V <sub>CSL5</sub> = 5.3V		2.5	mA
MAIN SMPS CONTROLLERS					
3.3V Output Voltage in Fixed Mode	V <sub>OUT3</sub>	$V_{IN} = 6V \text{ to } 26V, \overline{SKIP} = V_{CC} \text{ (Note 2)}$	3.28	3.38	V
5V Output Voltage in Fixed Mode	V <sub>OUT5</sub>	V <sub>IN</sub> = 6V to 26V, SKIP = V <sub>CC</sub> (Note 2)	4.975	5.125	V
Feedback Voltage in Adjustable Mode	V <sub>FB3</sub> , V <sub>FB5</sub>	V <sub>IN</sub> = 6V to 26V, FB3 or FB5, duty factor = 20% to 80% (Note 2)	0.982	1.018	V
Output-Voltage Adjust Range		Either SMPS	1.0	5.5	V
FB3, FB5 Adjustable-Mode Threshold Voltage		Dual-mode comparator	0.1	0.2	V

### **ELECTRICAL CHARACTERISTICS (continued)**

(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  $V_{LDO5}$  =

PARAMETER	SYMBOL	со	NDITIONS	MIN	MAX	UNITS
		FSEL = GND		170	230	
Operating Frequency (Note 1)	fosc	fosc FSEL = REF		240	330	kHz
		FSEL = V <sub>CC</sub>		375	575	
		FSEL = GND		91		
Maximum Duty Factor (Note 1)	D <sub>MAX</sub>	FSEL = REF		91		%
		FSEL = V <sub>CC</sub>		91		
Minimum On-Time	ton(MIN)				250	ns
CURRENT LIMIT						
ILIM_ Adjustment Range				0.5	V <sub>REF</sub>	V
Current-Limit Threshold (Fixed)	V <sub>LIMIT</sub> _	V <sub>CSH</sub> V <sub>CSL</sub> _, ILII	M_ = VCC	67	83	mV
			V <sub>ILIM</sub> _ = 2.00V	170	230	
Current-Limit Threshold	V <sub>LIMIT</sub> _	V <sub>CSH</sub> V <sub>CSL</sub> _	V <sub>ILIM</sub> _ = 1.00V	90	110	mV
(Adjustable)			V <sub>ILIM</sub> _ = 0.50V	40	60	
INTERNAL FIXED LINEAR REGU	LATORS					
LDO5 Output Voltage	V <sub>LDO5</sub>		ON3 = ON5 = GND, 6V < V <sub>IN</sub> < 26V, 0 < I <sub>LDO5</sub> < 100mA		5.1	٧
LDO5 Undervoltage-Lockout Fault Threshold		Rising edge, hyste	resis = 1%	3.75	4.30	٧
LDO3 Output Voltage	V <sub>LDO3</sub>	Standby mode, 6V 0 < I <sub>LOAD</sub> < 100mA		3.20	3.43	٧
<b>AUXILIARY LINEAR REGULATO</b>	R (MAX1537	ONLY)				
LDOA Voltage Range	V <sub>LODA</sub>			5	23	V
INA Voltage Range	VINA			6	24	V
LDOA Regulation Threshold, Internal Feedback		ADJA = GND, 0 < V <sub>INA</sub> > 13V	I <sub>LDOA</sub> < 120mA,	11.40	12.55	V
ADJA Regulation Threshold, External Feedback	V <sub>ADJA</sub>	0 < I <sub>LDOA</sub> < 120mA, V <sub>LDOA</sub> > 5.0V and V <sub>INA</sub> > V <sub>LDOA</sub> + 1V		1.94	2.08	V
ADJA Dual-Mode Threshold		ADJA		0.10	0.25	V
Secondary Feedback Regulation Threshold		VINA - VLDOA		0.63	0.97	V
INA Quiescent Current	I <sub>INA</sub>	V <sub>INA</sub> = 24V, I <sub>LDOA</sub> = no load			165	μΑ
REFERENCE (REF)	•					
Reference Voltage	V <sub>REF</sub>	$V_{CC} = 4.5V \text{ to } 5.5V$	/, I <sub>REF</sub> = 0	1.97	2.03	V

#### **ELECTRICAL CHARACTERISTICS (continued)**

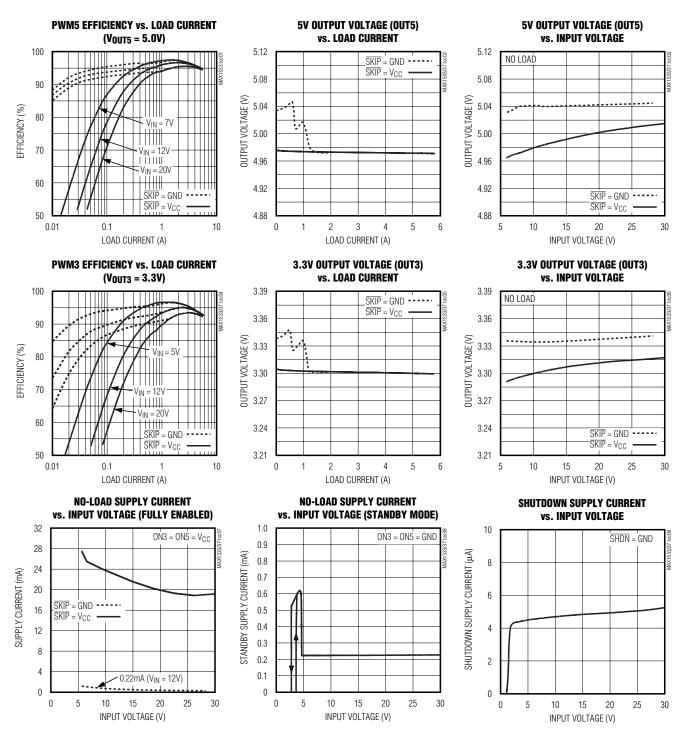
(Circuit of Figure 1,  $V_{IN}$  = 12V, both SMPS enabled,  $V_{CC}$  = 5V, FSEL = REF,  $\overline{SKIP}$  = GND,  $V_{ILIM}$  =  $V_{LDO5}$ ,  $V_{INA}$  = 15V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  =  5V,  $V_{LDOA}$  = 12V,  $V_{LDO5}$  = 12V,

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS		
FAULT DETECTION		·					
Output Overvoltage Trip Threshold		OVP = GND, with respect to comparator threshold	error-	+8	+15	%	
Output Undervoltage-Protection Trip Threshold		With respect to error-compa	rator threshold	+65	+75	%	
PGOOD Lower Trip Threshold		With respect to error-compa hysteresis = 1%	rator threshold,	-14.0	-7.0	%	
PGOOD Output Low Voltage		ISINK = 4mA			0.4	V	
PGDLY Pulldown Resistance					25	Ω	
PGDLY Trip Threshold				REF- 0.2	REF+ 0.2	٧	
GATE DRIVERS	•			•			
DH_ Gate-Driver On-Resistance	R <sub>DH</sub>	BST LX_ forced to 5V			5	Ω	
DL_ Gate-Driver On-Resistance	R <sub>DL</sub>	DL_, high state DL_, low state			5	Ω	
DL_ Gate-Driver On-nesistance	NDL				3	52	
INPUTS AND OUTPUTS							
Logic Input Voltage		SKIP, hysteresis = 600mV	High	2.4		V	
Logic input voltage		Orth, hysteresis – occini	Low		0.8	V	
Fault Enable Logic Input Voltage		OVP, UVP, ONA	High	0.7 x VCC		V	
			Low		0.4		
SHDN Input Trip Level		Rising trip level		1.1	2.2	V	
STIDIN INput Trip Level		Falling trip level		0.95	1.05	V	
		Clear fault level			0.8		
ON_ Input Voltage		SMPS off level			1.6	V	
ON_ Input Voltage		Delay start level (REF)		1.9	2.1	, v	
		SMPS on level		2.4			
		High		V <sub>CC</sub> - 0.2			
FSEL Three-Level Input Logic		REF		1.7	2.3	V	
		GND			0.4		

- Note 1: The MAX1533/MAX1537 cannot operate over all combinations of frequency, input voltage (V<sub>IN</sub>), and output voltage. For large input-to-output differentials and high-switching frequency settings, the required on-time may be too short to maintain the regulation specifications. Under these conditions, a lower operating frequency must be selected. The minimum on-time must be greater than 150ns, regardless of the selected switching frequency. On-time and off-time specifications are measured from 50% point to 50% point at the DH\_ pin with LX\_ = GND, VBST\_ = 5V, and a 250pF capacitor connected from DH\_ to LX\_. Actual in-circuit times may differ due to MOSFET switching speeds.
- Note 2: When the inductor is in continuous conduction, the output voltage has a DC regulation level lower than the error-comparator threshold by 50% of the ripple. In discontinuous conduction (SKIP = GND, light load), the output voltage has a DC regulation level higher than the trip level by approximately 1% due to slope compensation.
- Note 3: Specifications are guaranteed by design, not production tested.
- Note 4: Specifications to -40°C are guaranteed by design, not production tested.

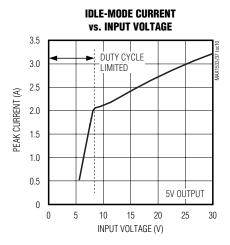
### **Typical Operating Characteristics**

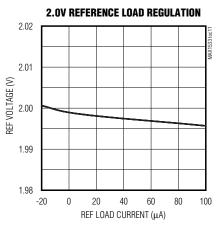
(MAX1537 circuit of Figure 1, VIN = 12V, LDO5 = VCC = 5V, SKIP = GND, FSEL = REF, TA = +25°C, unless otherwise noted.)

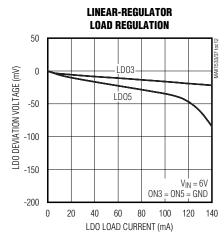


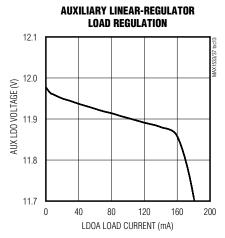
### Typical Operating Characteristics (continued)

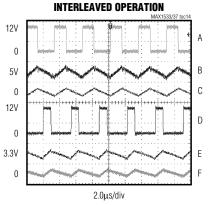
(MAX1537 circuit of Figure 1, V<sub>IN</sub> = 12V, LDO5 = V<sub>CC</sub> = 5V, SKIP = GND, FSEL = REF, T<sub>A</sub> = +25°C, unless otherwise noted.)





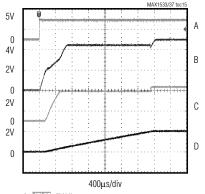






- A. LX5, 10V/div
- B. 5V OUTPUT, 100mV/div
- C. PWM5 INDUCTOR CURRENT, 5A/div
- D. LX3. 10V/div
- E. 3.3V OUTPUT, 100mV/div
- F. PWM3 INDUCTOR CURRENT, 5A/div

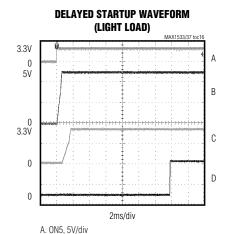




- A. SHDN, 5V/div
- B. LD05, 2V/div
- C. LD03, 2V/div
- D. RFF. 2V/div
- $100\Omega$  LOAD ON LD05 AND LD03

### Typical Operating Characteristics (continued)

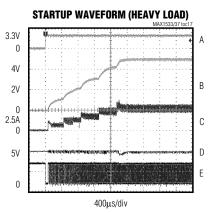
(MAX1537 circuit of Figure 1, V<sub>IN</sub> = 12V, LDO5 = V<sub>CC</sub> = 5V, SKIP = GND, FSEL = REF, T<sub>A</sub> = +25°C, unless otherwise noted.)



B. 5V OUTPUT, 2V/div

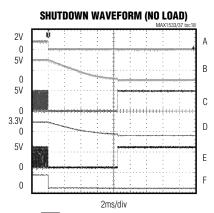
C. 3.3V OUPUT, 2V/div D. PGOOD, 2V/div

 $100\Omega$  LOAD ON OUT5 AND OUT3, ON3 = REF



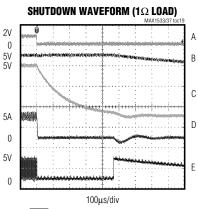
A. ON5, 5V/div B. 5V OUTPUT, 2V/div C. INDUCTOR CURRENT, 5A/div

D. LD05, 1V/div E. DL5, 5V/div  $1.0\Omega$  LOAD



A. SHDN, 5V/div D. 3.3V OUTPUT, 5V/div B. 5V OUTPUT, 5V/div E. DL3, 5V/div C. DL5, 5V/div F. PGOOD, 5V/div

 $ON3 = ON5 = V_{CC}, \overline{OVP} = GND$ 



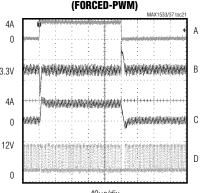
A. SHDN, 5V/div B. LD05, 2V/div C. 5V OUTPUT, 2V/div D. INDUCTOR CURRENT, 5A/div F DL5 5V/div  $ON3 = ON5 = V_{CC}, \overline{OVP} = GND$ 

### **5V OUTPUT LOAD TRANSIENT** (FORCED-PWM) 4A 0

C 0 12V D 0 40µs/div

A.  $I_{OUT5} = 0.2A TO 4A, 5A/div$ B.  $V_{OUT5} = 5.0V$ , 100mV/divC. INDUCTOR CURRENT, 5A/div D. LX5. 10V/div  $\overline{\text{SKIP}} = V_{CC}$ 

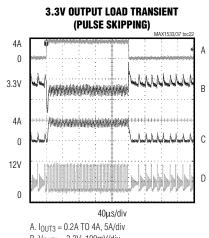
#### 3.3V OUTPUT LOAD TRANSIENT (FORCED-PWM)



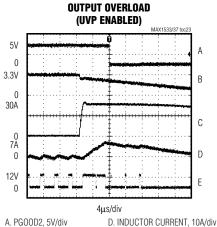
A. I<sub>OUT3</sub> = 0.2A TO 4A, 5A/div B.  $V_{OUT3} = 3.3V$ , 100 mV/divC. INDUCTOR CURRENT, 5A/div D. LX3, 10V/div  $\overline{SKIP} = V_{CC}$ 

### Typical Operating Characteristics (continued)

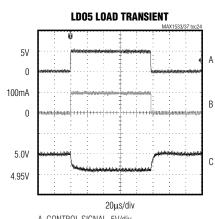
(MAX1537 circuit of Figure 1, V<sub>IN</sub> = 12V, LDO5 = V<sub>CC</sub> = 5V, SKIP = GND, FSEL = REF, T<sub>A</sub> = +25°C, unless otherwise noted.)



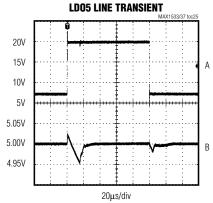
A.  $I_{OUT3} = 0.2A$  TO 4A, 5A/div B.  $V_{OUT3} = 3.3V$ , 100mV/div C. INDUCTOR CURRENT, 5A/div D. LX3, 10V/div  $\overline{SKIP} = GND$ 



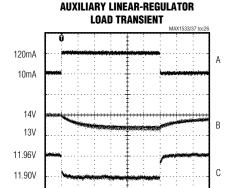
A. PG00D2, 5V/div D. INDUCTOR C
B. 3.3V 0UTPUT, 3.3V/div
C. LOAD (0 TO 30A), 20A/div



A. CONTROL SIGNAL, 5V/div B.  $I_{LD05} = 1$ mA TO 100mA, 100mA/div C. LD05, 50m/div ON3 = ON5 = GND



A. INPUT VOLTAGE ( $V_{IN}$  = 7V TO 20V), 5V/div B. LD05 OUTPUT VOLTAGE, 50mV/div ON3 = ON5 = GND,  $I_{LD05}$  = 20mA



A. I<sub>LDOA</sub> = 10mA TO 100mA, 100mA/div B. INA, 1V/div C. LDOA, 50mV/div INA = VOLTAGE GENERATED BY SECONDARY TRANSFORMER WINDING

100µs/div

### **Pin Description**

F	PIN		
MAX1533	MAX1537	NAME	FUNCTION
_	1	ADJA	Auxiliary Feedback Input. Connect a resistive voltage-divider from LDOA to analog ground to adjust the auxiliary linear-regulator output voltage. ADJA regulates at 2V. Connect ADJA to GND for nominal 12V output using internal feedback.
1	2	ON5	5V SMPS Enable Input. The 5V SMPS is enabled if ON5 is greater than the SMPS on level and disabled if ON5 is less than the SMPS off level. If ON5 is connected to REF, the 5V SMPS starts after the 3.3V SMPS reaches regulation (delay start). Drive ON5 below the clear fault level to reset the fault latches.
2	3	ON3	3.3V SMPS Enable Input. The 3.3V SMPS is enabled if ON3 is greater than the SMPS on level and disabled if ON3 is less than the SMPS off level. If ON3 is connected to REF, the 3.3V SMPS starts after the 5V SMPS reaches regulation (delay start). Drive ON3 below the clear fault level to reset the fault latches.
_	4	ONA	LDOA Enable Input. When ONA is low, LDOA is high impedance and the secondary winding control is off. When ONA is high, LDOA is on. Connect to LDO3, LDO5, CSL3, CSL5, or other output for desired automatic startup sequencing.
3	5	FSEL	Frequency-Select Input. This three-level logic input sets the controller's switching frequency. Connect to GND, REF, or $V_{CC}$ to select the following typical switching frequencies: $V_{CC} = 500 \text{kHz},  \text{REF} = 300 \text{kHz},  \text{GND} = 200 \text{kHz}$
4	6	ILIM3	3.3V SMPS Peak Current-Limit Threshold Adjustment. The current-limit threshold defaults to 75mV if ILIM3 is connected to $V_{\rm CC}$ . In adjustable mode, the current-limit threshold across CSH3 and CSL3 is precisely 1/10th the voltage seen at ILIM3 over a 500mV to 2.0V range. The logic threshold for switchover to the 75mV default value is approximately $V_{\rm CC}$ - 1V.
5	7	ILIM5	5V SMPS Peak Current-Limit Threshold. The current-limit threshold defaults to 75mV if ILIM5 is connected to V $_{\rm CC}$ . In adjustable mode, the current-limit threshold across CSH5 and CSL5 is precisely 1/10th the voltage seen at ILIM5 over a 500mV to 2.0V range. The logic threshold for switchover to the 75mV default value is approximately V $_{\rm CC}$ - 1V.
6	8	REF	2.0V Reference Voltage Output. Bypass REF to analog ground with a 0.1μF or greater ceramic capacitor. The reference can source up to 100μA for external loads. Loading REF degrades output-voltage accuracy according to the REF load-regulation error. The reference shuts down when SHDN is low.
7	9	GND	Analog Ground. Connect the backside pad to GND.
8	10	Vcc	Analog Supply Input. Connect to the system supply voltage (+4.5V to +5.5V) through a series $20\Omega$ resistor. Bypass V <sub>CC</sub> to analog ground with a 1µF or greater ceramic capacitor.
9	11	PGDLY	Power-Good One-Shot Delay. Place a timing capacitor on PGDLY to delay PGOOD going high. PGDLY has a $5\mu A$ pullup current and a $10\Omega$ pulldown. The pulldown is activated when power is not good. When power is good, the pulldown is shut off and the $5\mu A$ pullup is activated. When PGDLY crosses REF, PGOOD is enabled.

### Pin Description (continued)

P	PIN		
MAX1533	MAX1537	NAME	FUNCTION
10	12	PGOOD	Open-Drain Power-Good Output. PGOOD is low if either output is more than 10% (typ) below the normal regulation point, during soft-start, and in shutdown. PGOOD is delayed on the rising edge by the PGDLY one-shot timer. PGOOD becomes high impedance when both SMPS outputs are in regulation.
11	13	ŪVP	Undervoltage Fault-Protection Control. Connect $\overline{\text{UVP}}$ to GND to select the default overvoltage threshold of 70% of nominal. Connect to $V_{CC}$ to disable undervoltage protection and clear the undervoltage fault latch.
12	14	DH3	High-Side Gate-Driver Output for 3.3V SMPS. DH3 swings from LX3 to BST3.
13	15	BST3	Boost Flying-Capacitor Connection for 3.3V SMPS. Connect to an external capacitor and diode as shown in Figure 6. An optional resistor in series with BST3 allows the DH3 pullup current to be adjusted.
14	16	LX3	Inductor Connection for 3.3V SMPS. Connect LX3 to the switched side of the inductor. LX3 serves as the lower supply rail for the DH3 high-side gate driver.
15	17	OVP	Overvoltage Fault-Protection Control. Connect $\overline{\text{OVP}}$ to GND to select the default overvoltage threshold of +11% above nominal. Connect to $V_{CC}$ to disable overvoltage protection and clear the overvoltage fault latch.
16	18	CSH3	Positive Current-Sense Input for 3.3V SMPS. Connect to the positive terminal of the current-sense element. Figure 9 describes two different current-sensing options.
17	19	CSL3	Negative Current-Sense Input for 3.3V SMPS. Connect to the negative terminal of the current-sense element. Figure 9 describes two different current-sensing options. CSL3 also serves as the bootstrap input for LDO3.
18	20	FB3	Feedback Input for 3.3V SMPS. Connect to GND for fixed 3.3V output. In adjustable mode, FB3 regulates to 1V.
19	21	LDO3	3.3V Internal Linear-Regulator Output. Bypass with 2.2 $\mu$ F (min) (1 $\mu$ F/20mA). Provides 100mA (min). Power is taken from LDO5. If CSL3 is greater than 3V, the linear regulator shuts down and LDO3 connects to CSL3 through a 1 $\Omega$ switch rated for loads up to 200mA.
20	22	DL3	Low-Side Gate-Driver Output for 3.3V SMPS. DL3 swings from PGND to LDO5.
21	23	PGND	Power Ground
22	24	DL5	Low-Side Gate-Driver Output for 5V SMPS. DL5 swings from PGND to LDO5.
23	25	LDO5	5V Internal Linear-Regulator Output. Bypass with 2.2 $\mu$ F (min) (1 $\mu$ F/20mA). Provides power for the DL_ low-side gate drivers, the DH_ high-side drivers through the BST diodes, the PWM controller, logic, and reference through the V <sub>CC</sub> pin, as well as the LDO3 internal 3.3V linear regulator. Provides 100mA (min) for external loads (+25mA for gate drivers). If CSL5 is greater than 4.5V, the linear regulator shuts down and LDO5 connects to CSL5 through a 0.75 $\Omega$ switch rated for loads up to 200mA.
24	26	FB5	Feedback Input for 5V SMPS. Connect to GND for fixed 5V output. In adjustable mode, FB5 regulates to 1V.

### Pin Description (continued)

PIN			
MAX1533	MAX1537	NAME	FUNCTION
25	27	CSL5	Negative Current-Sense Input for 5V SMPS. Connect to the negative terminal of the current-sense element. Figure 9 describes two different current-sensing options. CSL5 also serves as the bootstrap input for LDO5.
26	28	CSH5	Positive Current-Sense Input for 5V SMPS. Connect to the positive terminal of the current-sense element. Figure 9 describes two different current-sensing options.
27	29	IN	Input of the Startup Circuitry and the LDO5 Internal 5V Linear Regulator. Bypass to PGND with 0.22µF close to the IC.
28	30	LX5	Inductor Connection for 5V SMPS. Connect LX5 to the switched side of the inductor. LX5 serves as the lower supply rail for the DH5 high-side gate driver.
29	31	BST5	Boost Flying-Capacitor Connection for 5V SMPS. Connect to an external capacitor and diode as shown in Figure 6. An optional resistor in series with BST5 allows the DH5 pullup current to be adjusted.
30	32	DH5	High-Side Gate-Driver Output for 5V SMPS. DH5 swings from LX5 to BST5.
31	33	SKIP	Pulse-Skipping Control Input. Connect to V <sub>CC</sub> for low-noise forced-PWM mode. Connect to GND for high-efficiency pulse-skipping mode at light loads.
32	34	SHDN	Shutdown Control Input. The device enters its 5µA supply-current shutdown mode if VSHDN is less than the SHDN input falling-edge trip level and does not restart until VSHDN is greater than the SHDN input rising-edge trip level. Connect SHDN to VIN for automatic startup. SHDN can be connected to VIN through a resistive voltage-divider to implement a programmable undervoltage lockout.
_	35	INA	Supply Voltage Input for the Auxiliary LDOA Linear Regulator. INA is clamped with an internal shunt to 26V.
_	36	LDOA	Adjustable (12V Nominal) 150mA Auxiliary Linear-Regulator Output. Input supply comes from INA. Bypass LDOA to GND with 2.2µF (min) (1µF/20mA). Secondary feedback threshold is set at INA - LDOA = 0.8V, and triggers the DL5 on the 5V SMPS only. ONA high enables regulator output and secondary regulation. PGOOD is not affected by the state of LDOA.

Table 1. Component Selection for Standard Applications

COMPONENT	5A/300kHz	5A/500kHz				
Input Voltage	V <sub>IN</sub> = 7V to 24V	V <sub>IN</sub> = 7V to 24V				
C <sub>IN_</sub> , Input Capacitor	(2) 10µF, 25V Taiyo Yuden TMK432BJ106KM	(2) 10µF, 25V Taiyo Yuden TMK432BJ106KM				
C <sub>OUT5</sub> , Output Capacitor	150μF, 6.3V, 40m $\Omega$ , low-ESR capacitor Sanyo 6TPB150ML	150μF, 6.3V, 40mΩ, low-ESR capacitor Sanyo 6TPB150ML				
C <sub>OUT3</sub> , Output Capacitor	220μF, 4V, 40mΩ, low-ESR capacitor Sanyo 4TPB220ML	220μF, 4V, 40mΩ, low-ESR capacitor Sanyo 4TPB220ML				
N <sub>H</sub> _ High-Side MOSFET	Fairchild Semiconductor FDS6612A International Rectifier IRF7807V	Fairchild Semiconductor FDS6612A International Rectifier IRF7807V				
N <sub>L_</sub> Low-Side MOSFET	Fairchild Semiconductor FDS6670S International Rectifier IRF7807VD1	Fairchild Semiconductor FDS6670S International Rectifier IRF7807VD1				
D <sub>L_</sub> Schottky Rectifier (if needed)	2A, 30V, 0.45V <sub>f</sub> Nihon EC21QS03L	2A, 30V, 0.45V <sub>f</sub> Nihon EC21QS03L				
Inductor/Transformer	T1 = 6.8µH, 1:2 turns Sumida 4749-T132 L1 = 5.8µH, 8.6A Sumida CDRH127-5R8NC	3.9µH Sumida CDRH124-3R9NC				
Rcs	10mΩ ±1%, 0.5W resistor IRC LR2010-01-R010F or Dale WSL-2010-R010F	10mΩ ±1%, 0.5W resistor IRC LR2010-01-R010F or Dale WSL-2010-R010F				

#### Table 2. Component Suppliers

SUPPLIER	WEBSITE
AVX	www.avx.com
Central Semiconductor	www.centralsemi.com
Coilcraft	www.coilcraft.com
Coiltronics	www.coiltronics.com
Fairchild Semiconductor	www.fairchildsemi.com
International Rectifier	www.irf.com
Kemet	www.kemet.com

### Detailed Description

The MAX1533/MAX1537 standard application circuit (Figure 1) generates the 5V/5A and 3.3V/5A typical of the main supplies in a notebook computer. The input supply range is 7V to 24V. See Table 1 for component selections and Table 2 for component manufacturers.

The MAX1533/MAX1537 contain two interleaved fixed-frequency step-down controllers designed for low-voltage power supplies. The optimal interleaved architecture guarantees out-of-phase operation, reducing the input capacitor ripple. Two internal LDOs generate the keep-alive 5V and 3.3V power. The MAX1537 has an auxiliary LDO that can be configured to the preset 12V output or an adjustable output.

SUPPLIER	WEBSITE
Panasonic	www.panasonic.com/industrial
Sanyo	www.secc.co.jp
Sumida	www.sumida.com
Taiyo Yuden	www.t-yuden.com
TDK	www.component.tdk.com
TOKO	www.tokoam.com
Vishay (Dale, Siliconix)	www.vishay.com

#### Fixed Linear Regulators (LDO5 and LDO3)

Two internal linear regulators produce preset 5V (LDO5) and 3.3V (LDO3) low-power outputs. LDO5 powers LDO3, the gate drivers for the external MOSFETs, and provides the bias supply (VCC) required for the SMPS analog control, reference, and logic blocks. LDO5 supplies at least 100mA for external and internal loads, including the MOSFET gate drive, which typically varies from 5mA to 50mA, depending on the switching frequency and external MOSFETs selected. LDO3 also supplies at least 100mA for external loads. Bypass LDO5 and LDO3 with a 2.2µF or greater output capacitor, using an additional 1.0µF per 20mA of internal and external load.

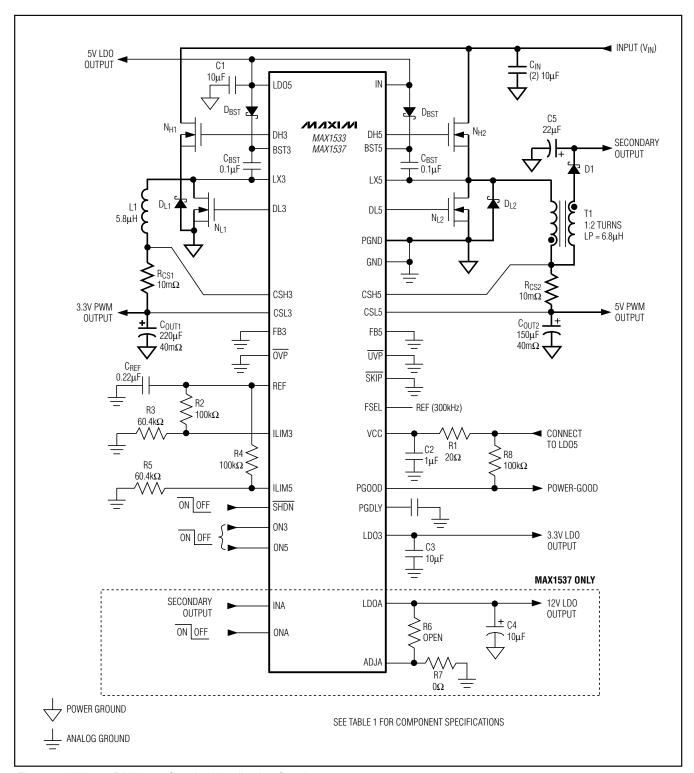


Figure 1. MAX1533/MAX1537 Standard Application Circuit

#### SMPS to LDO Bootstrap Switchover

When the 5V main output voltage is above the LDO5 bootstrap-switchover threshold, an internal  $0.75\Omega$  (typ) p-channel MOSFET shorts CSL5 to LDO5 while simultaneously shutting down the LDO5 linear regulator. Similarly, when the 3.3V main output voltage is above the LDO3 bootstrap-switchover threshold, an internal  $1\Omega$  (typ) p-channel MOSFET shorts CSL3 to LDO3 while simultaneously shutting down the LDO3 linear regulator. These actions bootstrap the device, powering the internal circuitry and external loads from the output SMPS voltages, rather than through linear regulators from the battery. Bootstrapping reduces power dissipation due to gate charge and quiescent losses by providing power from a 90%-efficient switch-mode source, rather than from a much-less-efficient linear regulator. The output current limit increases to 200mA when the LDO\_ outputs are switched over.

#### SMPS 5V Bias Supply (LDO5 and V<sub>CC</sub>)

The A switch-mode power supplies (SMPS) require a 5V bias supply in addition to the high-power input supply (battery or AC adapter). This 5V bias supply is generated by the MAX1533/MAX1537s' internal 5V linear regulator (LDO5). This bootstrapped LDO allows the MAX1533/MAX1537 to power-up independently. The gate-driver input supply is connected to the fixed 5V linear-regulator output (LDO5). Therefore, the 5V LDO supply must provide VCC (PWM controller) and the gate-drive power, so the maximum supply current required is:

IBIAS = ICC + fSW (QG(LOW) + QG(HIGH))= 5mA to 50mA (typ)

where I<sub>CC</sub> is 1mA (typ), f<sub>SW</sub> is the switching frequency, and Q<sub>G(LOW)</sub> and Q<sub>G(HIGH)</sub> are the MOSFET data sheet's total gate-charge specification limits at  $V_{GS} = 5V$ .

#### Reference (REF)

The 2V reference is accurate to  $\pm 1\%$  over temperature and load, making REF useful as a precision system reference. Bypass REF to GND with a  $0.22\mu\text{F}$  or greater ceramic capacitor. The reference sources up to  $100\mu\text{A}$  and sinks  $10\mu\text{A}$  to support external loads. If highly accurate specifications ( $\pm 0.5\%$ ) are required for the main SMPS output voltages, the reference should not be loaded. Loading the reference reduces the LDO5, LDO3, OUT5, and OUT3 output voltages slightly because of the reference load-regulation error.

#### System Enable/Shutdown (SHDN)

Drive SHDN below the precise SHDN input falling-edge trip level to place the MAX1533/MAX1537 in their low-power shutdown state. The MAX1533/MAX1537 consume only 5μA of quiescent current while in shutdown mode. When shutdown mode activates, the reference turns off, making the threshold to exit shutdown less accurate. To guarantee startup, drive SHDN above 2.2V (SHDN input rising-edge trip level). For automatic shutdown and startup, connect SHDN to VIN. The accurate 1V falling-edge threshold on SHDN can be used to detect a specific input-voltage level and shut the device down. Once in shutdown, the 1.6V rising-edge threshold activates, providing sufficient hysteresis for most applications.

### SMPS Detailed \_\_\_\_Description

#### SMPS POR, UVLO, and Soft-Start

Power-on reset (POR) occurs when  $V_{CC}$  rises above approximately 1V, resetting the undervoltage, overvoltage, and thermal-shutdown fault latches. The POR circuit also ensures that the low-side drivers are pulled low if OVP is disabled  $(\overline{OVP} = V_{CC})$ , or driven high if OVP is enabled  $(\overline{OVP} = GND)$  until the SMPS controllers are activated.

The V<sub>CC</sub> input undervoltage-lockout (UVLO) circuitry inhibits switching if the 5V bias supply (LDO5) is below the 4V input UVLO threshold. Once the 5V bias supply (LDO5) rises above this input UVLO threshold and the controllers are enabled, the SMPS controllers start switching and the output voltages begin to ramp up using soft-start.

The internal digital soft-start gradually increases the internal current-limit level during startup to reduce the input surge currents. The MAX1533/MAX1537 divide the soft-start period into five phases. During the first phase, each controller limits its current limit to only 20% of its full current limit. If the output does not reach regulation within 128 clock cycles (1 / fosc), soft-start enters the second phase and the current limit is increased by another 20%. This process repeats until the maximum current limit is reached after 512 clock cycles (1 / fosc) or when the output reaches the nominal regulation voltage, whichever occurs first (see the startup waveforms in the *Typical Operating Characteristics*).

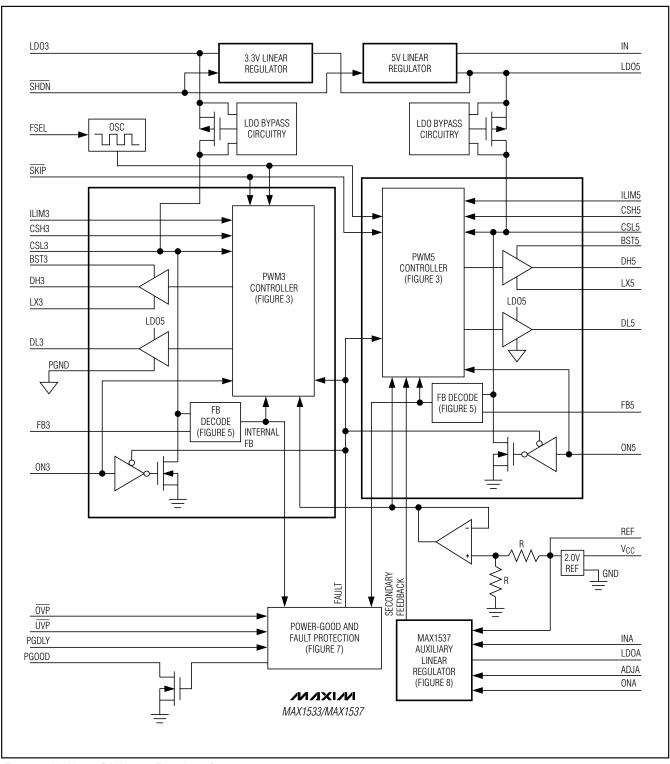


Figure 2. MAX1533/MAX1537 Functional Diagram

Table 3. Operating Modes

	1			1						
MODE		INPUTS*		OUTPUTS						
MODE	SHDN	ON5	ON3	LDO5	LDO3	5V SMPS	3V SMPS			
Shutdown Mode	LOW	Χ	Χ	OFF	OFF	OFF	OFF			
Standby Mode	HIGH	LOW	LOW	ON	ON	OFF	OFF			
Normal Operation	HIGH	HIGH	HIGH	ON	ON	ON	ON			
3.3V SMPS Active	HIGH	LOW	HIGH	ON	ON	OFF	ON			
5V SMPS Active	HIGH	HIGH	LOW	ON	ON	ON	OFF			
Normal Operation (Delayed 5V SMPS Startup)	HIGH	REF	HIGH	ON	ON	ON Power-up after 3.3V SMPS is in regulation	ON			
Normal Operation (Delayed 3.3V SMPS Startup)	(Delayed 3.3V HIGH		REF	ON	ON	ON	ON Power-up after 5V SMPS is in regulation			

<sup>\*</sup>SHDN is an accurate, low-voltage logic input with 1V falling-edge threshold voltage and 1.6V rising-edge threshold voltage. ON3 and ON5 are 3-level CMOS logic inputs, a logic-low voltage is less than 0.8V, a logic-high voltage is greater than 2.4V, and the middle logic level is between 1.9V and 2.1V (see the Electrical Characteristics table).

#### SMPS Enable Controls (ON3, ON5)

ON3 and ON5 control SMPS power-up sequencing. ON3 or ON5 rising above 2.4V enables the respective outputs. ON3 or ON5 falling below 1.6V disables the respective outputs. Driving ON\_ below 0.8V clears the overvoltage, undervoltage, and thermal fault latches.

#### SMPS Power-Up Sequencing

Connecting ON3 or ON5 to REF forces the respective outputs off while the other output is below regulation and starts after that output regulates. The second SMPS remains on until the first SMPS turns off, the device shuts down, a fault occurs, or LDO5 goes into undervoltage lockout. Both supplies begin their power-down sequence immediately when the first supply turns off.

#### Output Discharge (Soft-Shutdown)

When output discharge is enabled  $(\overline{\text{OVP}}\ \text{pulled low})$  and the switching regulators are disabled—by transitions into standby or shutdown mode, or when an output undervoltage fault occurs—the controller discharges both outputs through internal  $12\Omega$  switches, until the output voltages decrease to 0.3V. This slowly discharges the output capacitance, providing a soft-damped shutdown response. This eliminates the slightly negative output voltages caused by quickly discharging the output through the inductor and low-side MOSFET. When an SMPS output discharges to

0.3V, its low-side driver (DL\_) is forced high, clamping the respective SMPS output to GND. The reference remains active to provide an accurate threshold and to provide overvoltage protection. Both SMPS controllers contain separate soft-shutdown circuits.

When output discharge is disabled ( $\overline{OVP} = V_{CC}$ ), the low-side drivers (DL\_) and high-side drivers (DH\_) are both pulled low, forcing LX into a high-impedance state. Since the outputs are not actively discharged by the SMPS controllers, the output-voltage discharge rate is determined only by the output capacitance and load current.

### Fixed-Frequency, Current-Mode PWM Controller

The heart of each current-mode PWM controller is a multi-input, open-loop comparator that sums two signals: the output-voltage error signal with respect to the reference voltage and the slope-compensation ramp (Figure 3). The MAX1533/MAX1537 use a direct-summing configuration, approaching ideal cycle-to-cycle control over the output voltage without a traditional error amplifier and the phase shift associated with it. The MAX1533/MAX1537 use a relatively low loop gain, allowing the use of low-cost output capacitors. The low loop gain results in the -0.1% typical load-regulation error and helps reduce the output capacitor size and cost by shifting the unity-gain crossover frequency to a lower level.

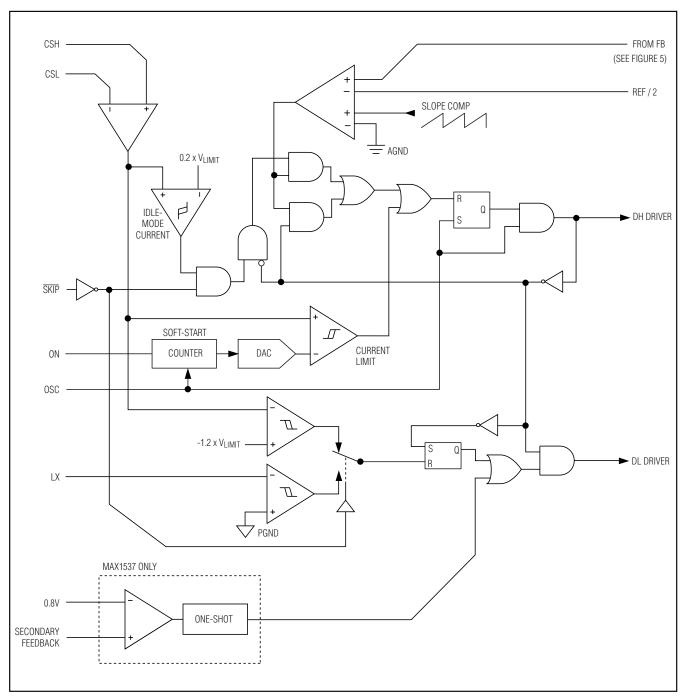


Figure 3: PWM-Controller Functional Diagram

#### Frequency Selection (FSEL)

The FSEL input selects the PWM-mode switching frequency. Table 4 shows the switching frequency based on FSEL connection. High-frequency (500kHz) operation optimizes the application for the smallest component size, trading off efficiency due to higher switching losses. This may be acceptable in ultra-portable devices where the load currents are lower. Low-frequency (200kHz) operation offers the best overall efficiency at the expense of component size and board space.

#### **Forced-PWM Mode**

The low-noise forced-PWM mode disables the zero-crossing comparator, which controls the low-side switch on-time. This forces the low-side gate-drive waveform to constantly be the complement of the high-side gate-drive waveform, so the inductor current reverses at light loads while DH\_ maintains a duty factor of  $V_{OUT}$  /  $V_{IN}$ . The benefit of forced-PWM mode is to keep the switching frequency fairly constant. However, forced-PWM operation comes at a cost: the no-load 5V supply current remains between 15mA and 50mA, depending on the external MOSFETs and switching frequency.

Forced-PWM mode is most useful for avoiding audiofrequency noise and improving load-transient response. Since forced-PWM operation disables the zero-crossing comparator, the inductor current reverses under light loads.

#### **Light-Load Operation Control (SKIP)**

The MAX1533/MAX1537 include a light-load operating-mode control input (SKIP) used to independently enable or disable the zero-crossing comparator for both controllers. When the zero-crossing comparator is enabled, the controller forces DL\_ low when the current-sense inputs detect zero inductor current. This keeps the inductor from discharging the output capacitors and forces the controller to skip pulses under light-load conditions to avoid overcharging the output. When the zero-crossing comparator is disabled, the controller is forced to maintain PWM operation under light-load conditions (forced-PWM).

Table 4. FSEL Configuration Table

FSEL	SWITCHING FREQUENCY
Vcc	500kHz
REF	300kHz
GND	200kHz

#### Idle-Mode Current-Sense Threshold

The on-time of the step-down controller terminates when the output voltage exceeds the feedback threshold and when the current-sense voltage exceeds the idle-mode current-sense threshold. Under light-load conditions, the on-time duration depends solely on the idle-mode current-sense threshold, which is approximately 20% of the full-load current-limit threshold set by ILIM\_. This forces the controller to source a minimum amount of power with each cycle. To avoid overcharging the output, another on-time cannot begin until the output voltage drops below the feedback threshold. Since the zero-crossing comparator prevents the switching regulator from sinking current, the controller must skip pulses. Therefore, the controller regulates the valley of the output ripple under light-load conditions.

#### Automatic Pulse-Skipping Crossover

In skip mode, an inherent automatic switchover to PFM takes place at light loads (Figure 4). This switchover is affected by a comparator that truncates the low-side switch on-time at the inductor current's zero crossing. The zero-crossing comparator senses the inductor current across the low-side MOSFET (PGND to LX\_). Once VPGND - VLX\_ drops below the 3mV zero-crossing current-sense threshold, the comparator forces DL\_ low (Figure 3). This mechanism causes the threshold between pulse-skipping PFM and nonskipping PWM operation to coincide with the boundary between continuous and discontinuous inductor-current operation (also known as the "critical conduction" point). The load-current level at which PFM/PWM crossover occurs, ILOAD(SKIP), is given by:

$$I_{LOAD(SKIP)} = \frac{V_{OUT} (V_{IN} - V_{OUT})}{2 \times V_{IN} \times f_{SW} \times L}$$

The switching waveforms may appear noisy and asynchronous when light loading causes pulse-skipping operation, but this is a normal operating condition that results in high light-load efficiency. Trade-offs in PFM noise vs. light-load efficiency are made by varying the inductor value. Generally, low inductor values produce a broader efficiency vs. load curve, while higher values result in higher full-load efficiency (assuming that the coil resistance remains fixed) and less output voltage ripple. Penalties for using higher inductor values include larger physical size and degraded load-transient response (especially at low input-voltage levels).

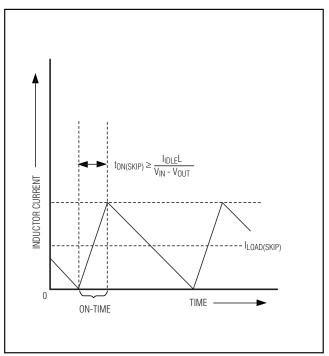


Figure 4. Pulse-Skipping/Discontinuous Crossover Point

**Output Voltage** 

DC output accuracy specifications in the *Electrical Characteristics* table refer to the error-comparator's threshold. When the inductor continuously conducts, the MAX1533/MAX1537 regulate the peak of the output ripple, so the actual DC output voltage is lower than the slope-compensated trip level by 50% of the output ripple voltage. For PWM operation (continuous conduction), the output voltage is accurately defined by the following equation:

$$V_{OUT(PWM)} = V_{NOM} \left( 1 - \frac{A_{SLOPE} V_{NOM}}{V_{IN}} \right) - \left( \frac{V_{RIPPLE}}{2} \right)$$

where  $V_{NOM}$  is the nominal output voltage, ASLOPE equals 1%, and  $V_{RIPPLE}$  is the output ripple voltage ( $V_{RIPPLE}$  = ESR x  $\Delta I_{INDUCTOR}$  as described in the Output Capacitor Selection section).

In discontinuous conduction (I<sub>OUT</sub> < I<sub>LOAD</sub>(SKIP)), the MAX1533/MAX1537 regulate the valley of the output ripple, so the output voltage has a DC regulation level higher than the error-comparator threshold. For PFM operation (discontinuous conduction), the output voltage is approximately defined by the following equation:

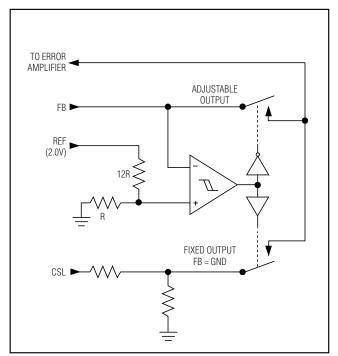


Figure 5. Dual-Mode Feedback Decoder

$$V_{OUT(PFM)} = V_{NOM} + \frac{1}{2} \left( \frac{f_{SW}}{f_{OSC}} \right) I_{IDLE} \times ESR$$

where V<sub>NOM</sub> is the nominal output voltage, f<sub>OSC</sub> is the maximum switching frequency set by the internal oscillator, f<sub>SW</sub> is the actual switching frequency, and I<sub>IDLE</sub> is the idle-mode inductor current when pulse skipping.

### Adjustable/Fixed Output Voltages (Dual-Mode Feedback)

Connect FB3 and FB5 to GND to enable the fixed SMPS output voltages (3.3V and 5V, respectively), set by a preset, internal resistive voltage-divider connected between CSL\_ and analog ground. Connect a resistive voltage-divider at FB\_ between CSL\_ and GND to adjust the respective output voltage between 1V and 5.5V (Figure 5). Choose R2 (resistance from FB to GND) to be about  $10 k\Omega$  and solve for R1 (resistance from OUT to FB) using the equation:

$$R1 = R2 \left( \frac{V_{OUT}}{V_{FB}} - 1 \right)$$

where  $V_{FB} = 1V$  nominal.

When adjusting both output voltages, set the 3.3V SMPS lower than the 5V SMPS. LDO5 connects to the 5V output (CSL5) through an internal switch only when CSL5 is above the LDO5 bootstrap threshold (4.56V). Similarly, LDO3 connects to the 3.3V output (CSL3) through an internal switch only when CSL3 is above the LDO3 bootstrap threshold (2.91V). Bootstrapping works most effectively when the fixed output voltages are used. Once LDO\_ is bootstrapped from CSL\_, the internal linear regulator turns off. This reduces internal power dissipation and improves efficiency at higher input voltage.

#### **Current-Limit Protection (ILIM\_)**

The current-limit circuit uses differential current-sense inputs (CSH\_ and CSL\_) to limit the peak inductor current. If the magnitude of the current-sense signal exceeds the current-limit threshold, the PWM controller turns off the high-side MOSFET (Figure 3). At the next rising edge of the internal oscillator, the PWM controller does not initiate a new cycle unless the current-sense signal drops below the current-limit threshold. The actual maximum load current is less than the peak current-limit threshold by an amount equal to half of the inductor ripple current. Therefore, the maximum load capability is a function of the current-sense resistance, inductor value, switching frequency, and duty cycle (VOUT / VIN).

In forced-PWM mode, the MAX1533/MAX1537 also implement a negative current limit to prevent excessive reverse inductor currents when VouT is sinking current. The negative current-limit threshold is set to approximately 120% of the positive current limit and tracks the positive current limit when ILIM\_ is adjusted.

Connect ILIM\_ to VCC for the 75mV default threshold, or adjust the current-limit threshold with an external resistor-divider at ILIM\_. Use a 2 $\mu A$  to 20 $\mu A$  divider current for accuracy and noise immunity. The current-limit threshold adjustment range is from 50mV to 200mV. In the adjustable mode, the current-limit threshold voltage equals precisely 1/10th the voltage seen at ILIM\_. The logic threshold for switchover to the 75mV default value is approximately VCC - 1V.

Carefully observe the PC board layout guidelines to ensure that noise and DC errors do not corrupt the differential current-sense signals seen by CSH\_ and CSL\_. Place the IC close to the sense resistor with short, direct traces, making a Kelvin-sense connection to the current-sense resistor.

#### **MOSFET Gate Drivers (DH\_, DL\_)**

The DH\_ and DL\_ drivers are optimized for driving moderate-sized high-side and larger low-side power MOSFETs. This is consistent with the low duty factor seen in notebook applications, where a large V<sub>IN</sub> - V<sub>OUT</sub> differential exists. The high-side gate drivers (DH\_) source and sink 2A, and the low-side gate drivers (DL\_) source 1.7A and sink 3.3A. This ensures robust gate drive for high-current applications. The DH\_ floating high-side MOSFET drivers are powered by diode-capacitor charge pumps at BST\_ (Figure 6) while the DL\_ synchronous-rectifier drivers are powered directly by the fixed 5V linear regulator (LDO5).

Adaptive dead-time circuits monitor the DL\_ and DH\_ drivers and prevent either FET from turning on until the other is fully off. The adaptive driver dead time allows operation without shoot-through with a wide range of MOSFETs, minimizing delays and maintaining efficiency. There must be a low-resistance, low-inductance path from the DL\_ and DH\_ drivers to the MOSFET gates for the adaptive dead-time circuits to work properly; otherwise, the sense circuitry in the MAX1533/MAX1537 interprets the MOSFET gates as "off" while charge actually remains. Use very short, wide traces (50 to 100 mils wide if the MOSFET is 1 inch from the driver).

The internal pulldown transistor that drives DL\_ low is robust, with a  $0.6\Omega$  (typ) on-resistance. This helps prevent DL\_ from being pulled up due to capacitive coupling from the drain to the gate of the low-side MOSFETs when the inductor node (LX\_) quickly switches from ground to V\_IN. Applications with high input voltages and long inductive driver traces may require additional gate-to-source capacitance to ensure fastrising LX\_ edges do not pull up the low-side MOSFETs' gate, causing shoot-through currents. The capacitive coupling between LX\_ and DL\_ created by the MOSFET's gate-to-drain capacitance (CRSS), gate-to-source capacitance (CISS - CRSS), and additional board parasitics should not exceed the following minimum threshold:

$$V_{GS(TH)} > V_{IN} \left( \frac{C_{RSS}}{C_{ISS}} \right)$$

Lot-to-lot variation of the threshold voltage may cause problems in marginal designs. Alternatively, adding a resistor less than  $10\Omega$  in series with BST\_ may remedy the problem by increasing the turn-on time of the high-side MOSFET without degrading the turn-off time (Figure 6).

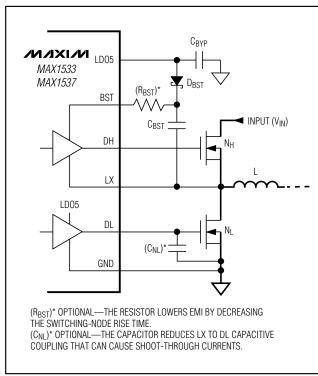


Figure 6. Optional Gate-Driver Circuitry

#### **Power-Good Output (PGOOD)**

PGOOD is the open-drain output of a comparator that continuously monitors both SMPS output voltages for undervoltage conditions. PGOOD is actively held low in shutdown (SHDN or ON3 or ON5 = GND), soft-start, and soft-shutdown. Once the digital soft-start terminates, PGOOD becomes high impedance as long as both outputs are above 90% of the nominal regulation voltage set by FB\_. PGOOD goes low once either SMPS output drops 10% below its nominal regulation point, an output overvoltage fault occurs, or either SMPS controller is shut down. For a logic-level PGOOD output voltage, connect an external pullup resistor between PGOOD and  $V_{\rm CC}$ . A  $100{\rm k}\Omega$  pullup resistor works well in most applications.

PGOOD is independent of the fault protection states  $\overline{\text{OVP}}$  and  $\overline{\text{UVP}}$ .

#### **Fault Protection**

#### Output Overvoltage Protection (OVP)

If the output voltage of either SMPS rises above 111% of its nominal regulation voltage and the OVP protection is enabled (OVP = GND), the controller sets the fault latch, pulls PGOOD low, shuts down both SMPS controllers, and immediately pulls DH\_ low and forces DL\_

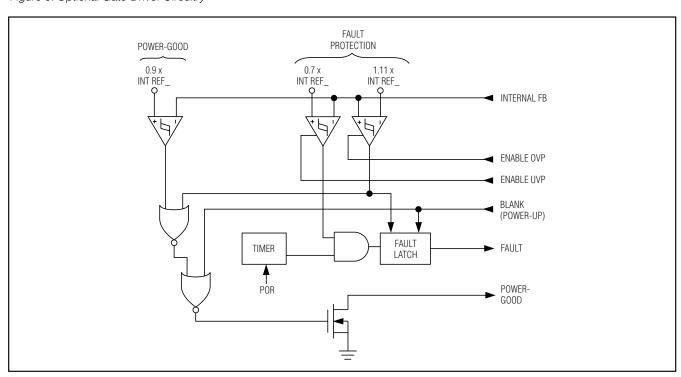


Figure 7. Power-Good and Fault Protection

high. This turns on the synchronous-rectifier MOSFETs with 100% duty, rapidly discharging the output capacitors and clamping both outputs to ground. However, immediately latching DL\_ high typically causes slightly negative output voltages due to the energy stored in the output LC at the instant the OVP occurs. If the load cannot tolerate a negative voltage, place a power Schottky diode across the output to act as a reverse-polarity clamp. If the condition that caused the overvoltage persists (such as a shorted high-side MOSFET), the battery fuse blows. Cycle VCC below 1V or toggle either ON3, ON5, or SHDN to clear the fault latch and restart the SMPS controllers.

Connect  $\overline{\text{OVP}}$  to VCC to disable the output overvoltage protection.

#### Output Undervoltage Protection (UVP)

Each SMPS controller includes an output UVP protection circuit that begins to monitor the output 6144 clock cycles (1 / fosc) after that output is enabled (ON\_pulled high). If either SMPS output voltage drops below 70% of its nominal regulation voltage and the UVP protection is enabled (UVP = GND), the UVP circuit sets the fault latch, pulls PGOOD low, and shuts down both controllers using discharge mode (see the *Output Discharge (Soft-Shutdown)* section). When an SMPS output voltage drops to 0.3V, its synchronous rectifier turns on, clamping the discharged output to GND. Cycle VCC below 1V or toggle either ON3, ON5, or SHDN to clear the fault latch and restart the SMPS controllers.

Connect  $\overline{\text{UVP}}$  to VCC to disable the output undervoltage protection.

**Table 5. Operating Modes Truth Table** 

MODE	CONDITION	COMMENT						
Power-Up	LDO5 < UVLO threshold.	Transitions to discharge mode after V <sub>IN</sub> POR and after REF becomes valid. LDO5, LDO3, REF remain active. DL_ is active if $\overrightarrow{OVP}$ is low.						
Run	SHDN = high, ON3 or ON5 enabled.	Normal operation.						
Output Overvoltage Protection (OVP)	Either output > 111% of nominal level, OVP = low.	Exited by POR or cycling SHDN, ON3, or ON5.						
Output Undervoltage Protection (UVP)	Either output < 70% of nominal level, UVP is enabled 6144 clock cycles (1 / fosc) after the output is enabled and $\overline{\text{UVP}}$ = low.	Exited by POR or cycling SHDN, ON3, or ON5. If OVP is not high, DL3 and DL5 go high after discharge.						
Discharge	OVP is low and either SMPS output is still high in either standby mode or shutdown mode.	Discharge switch ( $10\Omega$ ) connects CSL_ to PGND. This is a temporary state entered when LDO5 is undervoltage or on the way to output UVLO, standby, shutdown, or thermal-shutdown states. One SMPS can be in discharge mode while the other is in run mode. If both outputs are discharged to 0.3V (on CSL_), discharge mode transitions to the appropriate state.						
Standby	ON5 and ON3 < startup threshold, SHDN = high.	DL_ stays high if OVP is low. LDO3, LDO5 active.						
Shutdown	SHDN = low.	All circuitry off.						
Thermal Shutdown	T <sub>J</sub> > +160°C.	Exited by POR or cycling SHDN, ON3, or ON5.  If OVP is not high, DL3 and DL5 go high before LDO5 turns off.						
Switchover Fault	Excessive current on LDO3 or LDO5 switchover transistors.	Exited by POR or cycling SHDN, ON3, or ON5.  If OVP is not high, DL3 and DL5 go high before LDO5 turns of						

#### Thermal Fault Protection

The MAX1533/MAX1537 feature a thermal fault-protection circuit. When the junction temperature rises above +160°C, a thermal sensor activates the fault latch, pulls PGOOD low, and shuts down both SMPS controllers using discharge mode (see the *Output Discharge (Soft-Shutdown)* section). When an SMPS output voltage drops to 0.3V, its synchronous rectifier turns on, clamping the discharged output to GND. Cycle V<sub>CC</sub> below 1V or toggle either ON3, ON5, or SHDN to clear the fault latch and restart the controllers after the junction temperature cools by 15°C.

### Auxiliary LDO Detailed Description (MAX1537 Only)

The MAX1537 includes an auxiliary linear regulator that delivers up to 150mA of load current. The output (LDOA) can be preset to 12V, ideal for PCMCIA power requirements, and for biasing the gates of load switches in a portable device. In adjustable mode, LDOA can be set to anywhere from 5V to 23V. The auxiliary regulator has an independent ON/OFF control, allowing it to be shut down when not needed, reducing power consumption when the system is in a low-power state.

A flyback-winding control loop regulates a secondary winding output, improving cross-regulation when the primary output is lightly loaded or when there is a low input-output differential voltage. If VINA - VLDOA falls below 0.8V, the low-side switch is turned on for a time equal to 33% of the switching period. This reverses the inductor (primary) current, pulling current from the output filter capacitor and causing the flyback transformer to operate in forward mode. The low impedance presented by the transformer secondary in forward mode dumps current into the secondary output, charging up the secondary capacitor and bringing VINA - VI DOA back into regulation. The secondary feedback loop does not improve secondary output accuracy in normal flyback mode, where the main (primary) output is heavily loaded. In this condition, secondary output accuracy is determined by the secondary rectifier drop, transformer turns ratio, and accuracy of the main output voltage.

### Adjustable LDOA Voltage (Dual-Mode Feedback)

Connect ADJA to GND to enable the fixed, preset 12V auxiliary output. Connect a resistive voltage-divider at ADJA between LDOA and GND to adjust the respective output voltage between 5V and 23V (Figure 8). Choose R2 (resistance from ADJA to GND) to be approximately

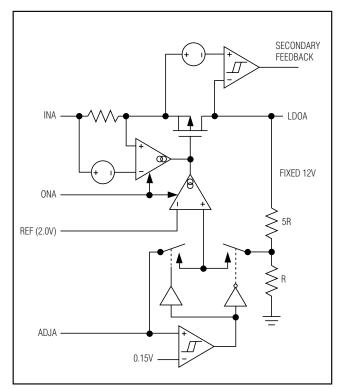


Figure 8. Linear-Regulator Functional Diagram

 $100k\Omega$  and solve for R1 (resistance from LDOA to ADJA) using the following equation:

$$R1 = R2 \left( \frac{V_{LDOA}}{V_{ADJA}} - 1 \right)$$

where  $V_{ADJA} = 2V$  nominal.

### **Design Procedure**

Firmly establish the input voltage range and maximum load current before choosing a switching frequency and inductor operating point (ripple-current ratio). The primary design trade-off lies in choosing a good switching frequency and inductor operating point, and the following four factors dictate the rest of the design:

Input Voltage Range. The maximum value (VIN(MAX)) must accommodate the worst-case, high AC-adapter voltage. The minimum value (VIN(MIN)) must account for the lowest battery voltage after drops due to connectors, fuses, and battery-selector switches. If there is a choice at all, lower input voltages result in better efficiency.

- Maximum Load Current. There are two values to consider. The peak load current (I<sub>LOAD</sub>(MAX)) determines the instantaneous component stresses and filtering requirements and thus drives output-capacitor selection, inductor saturation rating, and the design of the current-limit circuit. The continuous load current (I<sub>LOAD</sub>) determines the thermal stresses and thus drives the selection of input capacitors, MOSFETs, and other critical heat-contributing components.
- **Switching Frequency.** This choice determines the basic trade-off between size and efficiency. The optimal frequency is largely a function of maximum input voltage, due to MOSFET switching losses that are proportional to frequency and V<sub>IN</sub><sup>2</sup>. The optimum frequency is also a moving target, due to rapid improvements in MOSFET technology that are making higher frequencies more practical.
- Inductor Operating Point. This choice provides trade-offs between size vs. efficiency and transient response vs. output ripple. Low inductor values provide better transient response and smaller physical size, but also result in lower efficiency and higher output ripple due to increased ripple currents. The minimum practical inductor value is one that causes the circuit to operate at the edge of critical conduction (where the inductor current just touches zero with every cycle at maximum load). Inductor values lower than this grant no further size-reduction benefit. The optimum operating point is usually found between 20% and 50% ripple current. When pulse skipping (SKIP low and light loads), the inductor value also determines the load-current value at which PFM/PWM switchover occurs.

#### **Inductor Selection**

The switching frequency and inductor operating point determine the inductor value as follows:

$$L = \frac{V_{OUT} (V_{IN} - V_{OUT})}{V_{IN} f_{OSC} I_{LOAD(MAX)} LIR}$$

For example:  $I_{LOAD(MAX)} = 5A$ ,  $V_{IN} = 12V$ ,  $V_{OUT} = 5V$ ,  $f_{OSC} = 300kHz$ , 30% ripple current or LIR = 0.3.

$$L \ = \ \frac{5V \times (12V - 5V)}{12V \times 300 \text{kHz} \times 5A \times 0.3} \ = 6.50 \mu \text{H}$$

Find a low-loss inductor with the lowest possible DC resistance that fits in the allotted dimensions. Most inductor manufacturers provide inductors in standard values, such as 1.0µH, 1.5µH, 2.2µH, 3.3µH, etc. Also

look for nonstandard values, which can provide a better compromise in LIR across the input voltage range. If using a swinging inductor (where the no-load inductance decreases linearly with increasing current), evaluate the LIR with properly scaled inductance values. For the selected inductance value, the actual peak-to-peak inductor ripple current ( $\Delta$ INDUCTOR) is defined by:

$$\Delta I_{|NDUCTOR} = \frac{V_{OUT} (V_{|N} - V_{OUT})}{V_{|N} f_{OSC} L}$$

Ferrite cores are often the best choice, although powdered iron is inexpensive and can work well at 200kHz. The core must be large enough not to saturate at the peak inductor current (IPFAK):

$$I_{PEAK} = I_{LOAD(MAX)} + \frac{\Delta I_{INDUCTOR}}{2}$$

#### Transformer Design (For the MAX1537 Auxiliary Output)

A coupled inductor or transformer can be substituted for the inductor in the 5V SMPS to create an auxiliary output (Figure 1). The MAX1537 is particularly well suited for such applications because the secondary feedback threshold automatically triggers DL5 even if the 5V output is lightly loaded.

The power requirements of the auxiliary supply must be considered in the design of the main output. The transformer must be designed to deliver the required current in both the primary and the secondary outputs with the proper turns ratio and inductance. The power ratings of the synchronous-rectifier MOSFETs and the current limit in the MAX1537 must also be adjusted accordingly. Extremes of low input-output differentials, widely different output loading levels, and high turns ratios can further complicate the design due to parasitic transformer parameters such as interwinding capacitance, secondary resistance, and leakage inductance. Power from the main and secondary outputs is combined to get an equivalent current referred to the main output. Use this total current to determine the current limit (see the Setting the Current Limit section):

where I<sub>TOTAL</sub> is the equivalent output current referred to the main output, and P<sub>TOTAL</sub> is the sum of the output power from both the main output and the secondary output:

$$N = \frac{V_{SEC} + V_{FWD}}{V_{OUT5} + V_{RECT} + V_{SENSE}}$$

where LPRIMARY is the primary inductance, N is the transformer turns ratio, VSEC is the minimum required rectified secondary voltage, V<sub>FWD</sub> is the forward drop across the secondary rectifier, VOUT5(MIN) is the minimum value of the main output voltage, and VRECT is the on-state voltage drop across the synchronous-rectifier MOSFET. The transformer secondary return is often connected to the main output voltage instead of ground to reduce the necessary turns ratio. In this case, subtract V<sub>OUT5</sub> from the secondary voltage (V<sub>SEC</sub> - V<sub>OUT5</sub>) in the transformer turns-ratio equation above. The secondary diode in coupled-inductor applications must withstand flyback voltages greater than 60V. Common silicon rectifiers, such as the 1N4001, are also prohibited because they are too slow. Fast silicon rectifiers such as the MURS120 are the only choice. The flyback voltage across the rectifier is related to the VIN - VOUT difference, according to the transformer turns ratio:

where N is the transformer turns ratio (secondary windings/primary windings), and V<sub>SEC</sub> is the maximum secondary DC output voltage. If the secondary winding is returned to V<sub>OUT5</sub> instead of ground, subtract V<sub>OUT5</sub> from V<sub>FLYBACK</sub> in the equation above. The diode's reverse-breakdown voltage rating must also accommodate any ringing due to leakage inductance. The diode's current rating should be at least twice the DC load current on the secondary output.

#### **Transient Response**

The inductor ripple current also impacts transient-response performance, especially at low  $V_{\text{IN}}$  -  $V_{\text{OUT}}$  differentials. Low inductor values allow the inductor current to slew faster, replenishing charge removed from the output filter capacitors by a sudden load step. The total output voltage sag is the sum of the voltage sag while the inductor is ramping up, and the voltage sag before the next pulse can occur.

$$V_{SAG} = \frac{L \left(\Delta I_{LOAD(MAX)}\right)^{2}}{2C_{OUT} \left(V_{IN} \times D_{MAX} - V_{OUT}\right)} + \frac{\Delta I_{LOAD(MAX)} \left(T - \Delta T\right)}{C_{OUT}}$$

where  $D_{MAX}$  is the maximum duty factor (see the Electrical Characteristics table), T is the switching period

(1 / fosc), and  $\Delta T$  equals Vout / Vin x T when in PWM mode, or L x 0.2 x IMAX / (Vin - Vout) when in skip mode. The amount of overshoot during a full-load to noload transient due to stored inductor energy can be calculated as:

$$V_{SOAR} = \frac{\left(\Delta I_{LOAD(MAX)}\right)^2 L}{2C_{OUT} V_{OUT}}$$

#### **Setting the Current Limit**

The minimum current-limit threshold must be great enough to support the maximum load current when the current limit is at the minimum tolerance value. The peak inductor current occurs at ILOAD(MAX) plus half the ripple current; therefore:

$$I_{\text{LIMIT}} > I_{\text{LOAD(MAX)}} + \left(\frac{\Delta I_{\text{INDUCTOR}}}{2}\right)$$

where  $I_{\text{LIMIT}}$  equals the minimum current-limit threshold voltage divided by the current-sense resistance (RSENSE). For the default setting, the minimum current-limit threshold is 70mV.

Connect ILIM\_ to VCC for the default current-limit threshold. In adjustable mode, the current-limit threshold is precisely 1/10th the voltage seen at ILIM\_. For an adjustable threshold, connect a resistive divider from REF to analog ground (GND) with ILIM\_ connected to the center tap. The external 500mV to 2V adjustment range corresponds to a 50mV to 200mV current-limit threshold. When adjusting the current limit, use 1% tolerance resistors and a divider current of approximately  $10\mu A$  to prevent significant inaccuracy in the current-limit tolerance.

The current-sense method (Figure 9) and magnitude determine the achievable current-limit accuracy and power loss. Typically, higher current-sense limits provide tighter accuracy, but also dissipate more power. Most applications employ a current-limit threshold (VLIMIT) of 50mV to 100mV, so the sense resistor can be determined by:

For the best current-sense accuracy and overcurrent protection, use a 1% tolerance current-sense resistor between the inductor and output as shown in Figure 9a. This configuration constantly monitors the inductor current, allowing accurate current-limit protection.

Alternatively, high-power applications that do not require highly accurate current-limit protection may reduce the overall power dissipation by connecting a series RC circuit across the inductor (Figure 9b) with an equivalent time constant:

$$\frac{L}{R_{I}} = C_{EQ} \times R_{EQ}$$

where  $R_L$  is the inductor's series DC resistance. In this configuration, the current-sense resistance equals the inductor's DC resistance ( $R_{SENSE} = R_L$ ). Use the worst-case inductance and  $R_L$  values provided by the induc-

tor manufacturer, adding some margin for the inductance drop over temperature and load.

#### **Output Capacitor Selection**

The output filter capacitor must have low enough equivalent series resistance (ESR) to meet output ripple and load-transient requirements, yet have high enough ESR to satisfy stability requirements. The output capacitance must be high enough to absorb the inductor energy while transitioning from full-load to no-load conditions without tripping the overvoltage fault protection. When using high-capacitance, low-ESR capacitors (see the *Output-Capacitor Stability Considerations* section),

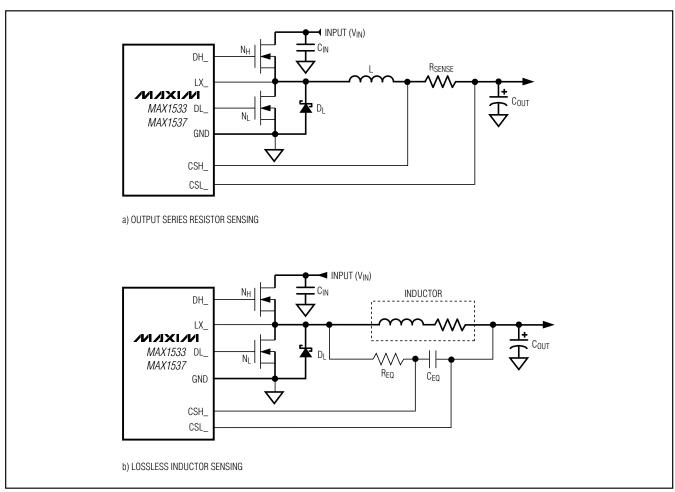


Figure 9. Current-Sense Configurations

the filter capacitor's ESR dominates the output voltage ripple. So the output capacitor's size depends on the maximum ESR required to meet the output voltage ripple (V<sub>RIPPLE(P-P)</sub>) specifications:

$$V_{RIPPLE(P-P)} = R_{ESR} I_{LOAD(MAX)} LIR$$

In idle mode, the inductor current becomes discontinuous, with peak currents set by the idle-mode current-sense threshold ( $V_{\rm IDLE}=0.2V_{\rm LIMIT}$ ). In idle mode, the no-load output ripple can be determined as follows:

$$V_{RIPPLE(P-P)} = \frac{V_{IDLE} R_{ESR}}{R_{SENSE}}$$

The actual capacitance value required relates to the physical size needed to achieve low ESR, as well as to the chemistry of the capacitor technology. Thus, the capacitor is usually selected by ESR and voltage rating rather than by capacitance value (this is true of tantalums, OS-CONs, polymers, and other electrolytics). When using low-capacity filter capacitors, such as ceramic capacitors, size is usually determined by the capacity needed to prevent VSAG and VSOAR from causing problems during load transients. Generally, once enough capacitance is added to meet the overshoot requirement, undershoot at the rising load edge is no longer a problem (see the VSAG and VSOAR equations in the Transient Response section). However, lowcapacity filter capacitors typically have high-ESR zeros that may affect the overall stability (see the Output-Capacitor Stability Considerations).

#### Output-Capacitor Stability Considerations

Stability is determined by the value of the ESR zero relative to the switching frequency. The boundary of instability is given by the following equation:

$$f_{ESR} \leq \frac{f_{OSC}}{\pi}$$
 where  $f_{ESR} = \frac{1}{2\pi~R_{ESR}~C_{OUT}}$ 

For a typical 300kHz application, the ESR zero frequency must be well below 95kHz, preferably below 50kHz. Tantalum and OS-CON capacitors in widespread use at the time of publication have typical ESR zero frequencies of 25kHz. In the design example used for inductor selection, the ESR needed to support 25mVp-p ripple is 25mV / 1.5A = 16.7m $\Omega$ . One 220 $\mu$ F/4V Sanyo polymer (TPE) capacitor provides 15m $\Omega$  (max) ESR. This results in a zero at 48kHz, well within the bounds of stability.

For low-input-voltage applications where the duty cycle exceeds 50% ( $V_{OUT}$  /  $V_{IN} \ge 50$ %), the output ripple voltage should not be greater than twice the internal slope-compensation voltage:

where VRIPPLE equals  $\Delta$ INDUCTOR x RESR. The worst-case ESR limit occurs when VIN = 2 x VOUT, so the above equation can be simplified to provide the following boundary condition:

Do not put high-value ceramic capacitors directly across the feedback sense point without taking precautions to ensure stability. Large ceramic capacitors can have a high-ESR zero frequency and cause erratic, unstable operation. However, it is easy to add enough series resistance by placing the capacitors a couple of inches downstream from the feedback sense point, which should be as close as possible to the inductor.

Unstable operation manifests itself in two related but distinctly different ways: short/long pulses or cycle skipping resulting in a lower switching frequency. Instability occurs due to noise on the output or because the ESR is so low that there is not enough voltage ramp in the output voltage signal. This "fools" the error comparator into triggering too early or skipping a cycle. Cycle skipping is more annoying than harmful, resulting in nothing worse than increased output ripple. However, it can indicate the possible presence of loop instability due to insufficient ESR. Loop instability can result in oscillations at the output after line or load steps. Such perturbations are usually damped, but can cause the output voltage to rise above or fall below the tolerance limits.

The easiest method for checking stability is to apply a very fast zero-to-max load transient and carefully observe the output-voltage-ripple envelope for overshoot and ringing. It can help to simultaneously monitor the inductor current with an AC-current probe. Do not allow more than one cycle of ringing after the initial step-response under/overshoot.

#### Input Capacitor Selection

The input capacitor must meet the ripple current requirement (I<sub>RMS</sub>) imposed by the switching currents. For an out-of-phase regulator, the total RMS current in the input capacitor is a function of the load currents, the input currents, the duty cycles, and the amount of overlap as defined in Figure 10.

The 40/60 optimal interleaved architecture of the MAX1533/MAX1537 allows the input voltage to go as low as 8.3V before the duty cycles begin to overlap.

This offers improved efficiency over a regular 180° outof-phase architecture where the duty cycles begin to overlap below 10V. Figure 10 shows the input-capacitor RMS current vs. input voltage for an application that requires 5V/5A and 3.3V/5A. This shows the improvement of the 40/60 optimal interleaving over 50/50 interleaving and in-phase operation.

For most applications, nontantalum chemistries (ceramic, aluminum, or OS-CON) are preferred due to their resistance to power-up surge currents typical of systems with a mechanical switch or connector in series with the input. Choose a capacitor that has less than 10°C temperature rise at the RMS input current for optimal reliability and lifetime.

#### **Power-MOSFET Selection**

Most of the following MOSFET guidelines focus on the challenge of obtaining high load-current capability when using high-voltage (>20V) AC adapters. Low-current applications usually require less attention.

The high-side MOSFET (N<sub>H</sub>) must be able to dissipate the resistive losses plus the switching losses at both  $V_{IN(MIN)}$  and  $V_{IN(MAX)}$ . Ideally, the losses at  $V_{IN(MIN)}$  should be roughly equal to the losses at  $V_{IN(MAX)}$ , with lower losses in between. If the losses at  $V_{IN(MIN)}$  are

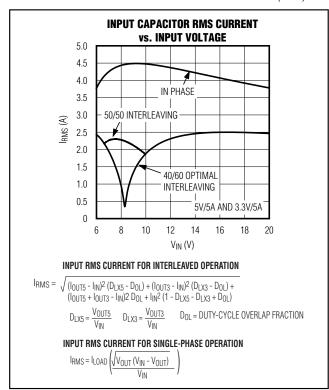


Figure 10. Input RMS Current

significantly higher, consider increasing the size of  $N_H$ . Conversely, if the losses at  $V_{IN(MAX)}$  are significantly higher, consider reducing the size of  $N_H$ . If  $V_{IN}$  does not vary over a wide range, maximum efficiency is achieved by selecting a high-side MOSFET ( $N_H$ ) that has conduction losses equal to the switching losses.

Choose a low-side MOSFET (N<sub>L</sub>) that has the lowest possible on-resistance (R<sub>DS(ON)</sub>), comes in a moderate-sized package (i.e., SO-8, DPAK, or D<sup>2</sup>PAK), and is reasonably priced. Ensure that the MAX1533/MAX1537 DL\_ gate driver can supply sufficient current to support the gate charge and the current injected into the parasitic drain-to-gate capacitor caused by the high-side MOSFET turning on; otherwise, cross-conduction problems may occur. Switching losses are not an issue for the low-side MOSFET since it is a zero-voltage switched device when used in the step-down topology.

#### **Power-MOSFET Dissipation**

Worst-case conduction losses occur at the duty factor extremes. For the high-side MOSFET (NH), the worst-case power dissipation due to resistance occurs at minimum input voltage:

PD (N<sub>H</sub> Resistive) = 
$$\left(\frac{V_{OUT}}{V_{IN}}\right) (I_{LOAD})^2 R_{DS(ON)}$$

Generally, use a small high-side MOSFET to reduce switching losses at high input voltages. However, the RDS(ON) required to stay within package power-dissipation limits often limits how small the MOSFET can be. The optimum occurs when the switching losses equal the conduction (RDS(ON)) losses. High-side switching losses do not become an issue until the input is greater than approximately 15V.

Calculating the power dissipation in high-side MOSFETs (N<sub>H</sub>) due to switching losses is difficult, since it must allow for difficult-to-quantify factors that influence the turn-on and turn-off times. These factors include the internal gate resistance, gate charge, threshold voltage, source inductance, and PC board layout characteristics. The following switching loss calculation provides only a very rough estimate and is no substitute for breadboard evaluation, preferably including verification using a thermocouple mounted on N<sub>H</sub>:

PD (N<sub>H</sub> Switching) = 
$$\frac{\left(V_{IN(MAX)}\right)^{2}C_{RSS} f_{SW} I_{LOAD}}{I_{GATE}}$$

where  $C_{RSS}$  is the reverse transfer capacitance of  $N_{H}$ , and  $I_{GATE}$  is the peak gate-drive source/sink current (1A typ).

Switching losses in the high-side MOSFET can become a heat problem when maximum AC-adapter voltages are applied, due to the squared term in the switching-loss equation (C x  $V_{IN}^2$  x fsw). If the high-side MOSFET chosen for adequate  $R_{DS(ON)}$  at low battery voltages becomes extraordinarily hot when subjected to  $V_{IN(MAX)}$ , consider choosing another MOSFET with lower parasitic capacitance.

For the low-side MOSFET (N<sub>L</sub>), the worst-case power dissipation always occurs at maximum battery voltage:

PD (N<sub>L</sub> Resistive) = 
$$\left[1 - \left(\frac{V_{OUT}}{V_{IN(MAX)}}\right)\right] (I_{LOAD})^2 R_{DS(ON)}$$

The absolute worst case for MOSFET power dissipation occurs under heavy-overload conditions that are greater than I<sub>LOAD(MAX)</sub> but are not high enough to exceed the current limit and cause the fault latch to trip. To protect against this possibility, "overdesign" the circuit to tolerate:

$$I_{LOAD} = I_{LIMIT} - \left(\frac{\Delta I_{INDUCTOR}}{2}\right)$$

where I<sub>LIMIT</sub> is the peak current allowed by the current-limit circuit, including threshold tolerance and sense-resistance variation. The MOSFETs must have a relatively large heatsink to handle the overload power dissipation.

Choose a Schottky diode (D<sub>L</sub>) with a forward-voltage drop low enough to prevent the low-side MOSFET's body diode from turning on during the dead time. As a general rule, select a diode with a DC current rating equal to 1/3rd the load current. This diode is optional and can be removed if efficiency is not critical.

#### **Boost Capacitors**

The boost capacitors (CBST) must be selected large enough to handle the gate-charging requirements of the high-side MOSFETs. Typically, 0.1 $\mu$ F ceramic capacitors work well for low-power applications driving medium-sized MOSFETs. However, high-current applications driving large, high-side MOSFETs require boost capacitors larger than 0.1 $\mu$ F. For these applications, select the boost capacitors to avoid discharging the capacitor more than 200mV while charging the high-side MOSFETs' gates:

$$C_{BST} = \frac{Q_{GATE}}{200mV}$$

where  $Q_{GATE}$  is the total gate charge specified in the high-side MOSFET's data sheet. For example, assume the FDS6612A n-channel MOSFET is used on the high side. According to the manufacturer's data sheet, a single FDS6612A has a maximum gate charge of 13nC (V<sub>GS</sub> = 5V). Using the above equation, the required boost capacitance is:

$$C_{BST} = \frac{13nC}{200mV} = 0.065\mu F$$

Selecting the closest standard value. This example requires a 0.1µF ceramic capacitor.

### Applications Information

#### **Duty-Cycle Limits**

#### Minimum Input Voltage

The minimum input operating voltage (dropout voltage) is restricted by the maximum duty-cycle specification (see the *Electrical Characteristics* table). However, keep in mind that the transient performance gets worse as the step-down regulators approach the dropout voltage, so bulk output capacitance must be added (see the voltage sag and soar equations in the *Design Procedure* section). The absolute point of dropout occurs when the inductor current ramps down during the off-time ( $\Delta I_{DOWN}$ ) as much as it ramps up during the on-time ( $\Delta I_{UP}$ ). This results in a minimum operating voltage defined by the following equation:

$$V_{IN(MIN)} = V_{OUT} + V_{CHG} + h \left(\frac{1}{D_{MAX}} - 1\right) (V_{OUT} + V_{DIS})$$

where  $V_{CHG}$  and  $V_{DIS}$  are the parasitic voltage drops in the charge and discharge paths, respectively. A reasonable minimum value for h is 1.5, while the absolute minimum input voltage is calculated with h = 1.

#### Maximum Input Voltage

The MAX1533/MAX1537 controllers include a minimum on-time specification, which determines the maximum input operating voltage that maintains the selected switching frequency (see the *Electrical Characteristics* table). Operation above this maximum input voltage results in pulse-skipping operation, regardless of the operating mode selected by SKIP. At the beginning of each cycle, if the output voltage is still above the feed-

back-threshold voltage, the controller does not trigger an on-time pulse, effectively skipping a cycle. This allows the controller to maintain regulation above the maximum input voltage, but forces the controller to effectively operate with a lower switching frequency. This results in an input threshold voltage at which the controller begins to skip pulses (VIN(SKIP)):

$$V_{IN(SKIP)} = V_{OUT} \left( \frac{1}{f_{OSC} t_{ON(MIN)}} \right)$$

where fosc is the switching frequency selected by FSEL.

#### **PC Board Layout Guidelines**

Careful PC board layout is critical to achieving low switching losses and clean, stable operation. The switching power stage requires particular attention (Figure 11). If possible, mount all of the power components on the top side of the board, with their ground terminals flush against one another. Follow these guidelines for good PC board layout:

- Keep the high-current paths short, especially at the ground terminals. This practice is essential for stable, jitter-free operation.
- Keep the power traces and load connections short. This practice is essential for high efficiency. Using thick copper PC boards (2oz vs. 1oz) can enhance full-load efficiency by 1% or more. Correctly routing PC board traces is a difficult task that must be approached in terms of fractions of centimeters, where a single  $\text{m}\Omega$  of excess trace resistance causes a measurable efficiency penalty.
- Minimize current-sensing errors by connecting CSH\_ and CSL\_ directly across the current-sense resistor (RSENSE\_).

- When trade-offs in trace lengths must be made, it is preferable to allow the inductor charging path to be made longer than the discharge path. For example, it is better to allow some extra distance between the input capacitors and the high-side MOSFET than to allow distance between the inductor and the lowside MOSFET or between the inductor and the output filter capacitor.
- Route high-speed switching nodes (BST\_, LX\_, DH\_, and DL\_) away from sensitive analog areas (REF, FB\_, CSH\_, CSL\_).

#### **Layout Procedure**

- Place the power components first, with ground terminals adjacent (N<sub>L</sub> source, C<sub>IN</sub>, C<sub>OUT</sub>, and D<sub>L</sub> anode). If possible, make all these connections on the top layer with wide, copper-filled areas.
- 2) Mount the controller IC adjacent to the low-side MOSFET, preferably on the back side opposite N<sub>L</sub> and N<sub>H</sub> to keep LX\_, GND, DH\_, and the DL\_ gatedrive lines short and wide. The DL\_ and DH\_ gate traces must be short and wide (50 to 100 mils wide if the MOSFET is 1 inch from the controller IC) to keep the driver impedance low and for proper adaptive dead-time sensing.
- Group the gate-drive components (BST\_ diode and capacitor, LDO5 bypass capacitor) together near the controller IC.
- 4) Make the DC-DC controller ground connections as shown in Figures 1 and 11. This diagram can be viewed as having two separate ground planes: power ground, where all the high-power components go; and an analog ground plane for sensitive analog components. The analog ground plane and power ground plane must meet only at a single point directly at the IC.
- 5) Connect the output power planes directly to the output-filter-capacitor positive and negative terminals with multiple vias. Place the entire DC-DC converter circuit as close to the load as is practical.

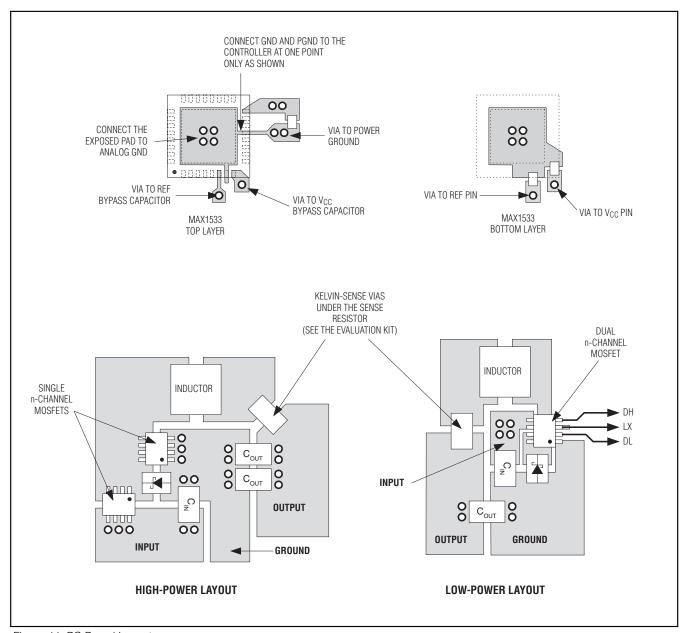
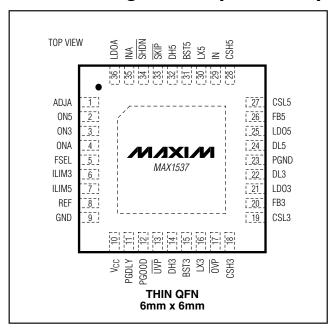


Figure 11. PC Board Layout

### Pin Configurations (continued)

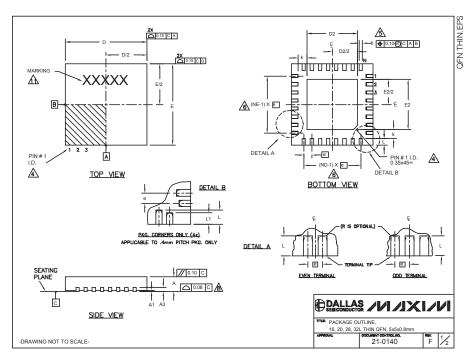
\_Chip Information

TRANSISTOR COUNT: 6890 PROCESS: BICMOS



### **Package Information**

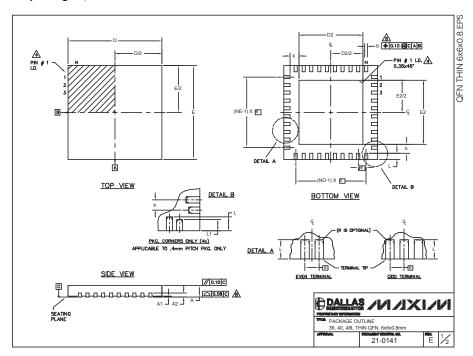
(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to www.maxim-ic.com/packages.)



A (0 A1 A3 b (0 D A4 E A4	0.70 ( 0 ( 0.2)	0.02 0.	XX. MIN. 80 0.70	-			8L 5x				- 1	- 1									
A (0 A1 A3 b (0 D A4 E A4	0.70 ( 0 ( 0.2)	0.75 0.	80 0.70	-	MAX.			:5	3	2L 5x	:5	ı	PKG	D2		E2			L	DOWN	
A1 A3 b 0 D 4 E 4 e k 0	0.20	0.02 0.		0.75		MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		CODES	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	±0.15	BONDS ALLOWED
A3 b 0 D 4 E 4 e k 0	0.20		05 0		0.80	0.70	0.75	0.80	0.70	0.75	0.80		T1655-1	3.00	3.10	3.20	3.00	3.10	3.20	**	NO
b (0 D 2 E 2 e	0.25		05 0	0.02	0.05	0	0.02	0.05	0	0.02	0.05		T1655-2	3.00	3.10	3.20	3.00	3.10	3.20	**	YES
D 2 E 2 e k (			(	).20 RE	F.	0.3	20 RE	F.	0	20 RE	F.		T1655N-1	3.00	3.10	3.20	3.00	3.10	3.20	**	NO
D 2 E 2 e k (		30 0	35 0.25	_	0.35	_	_	0.30	0.20	_	0.30	L	T2055-2	3.00	3.10	3.20	3.00	3.10	3.20	**	NO
E 4			10 4.90		5.10	0		5.10	4.90	5.00	5.10	L	T2055-3	3.00	3.10	3.20	3.00	3.10	3.20	**	YES
k (			10 4.90		5.10	_	0.00	_	4.90	-	5.10		T2055-4	3.00	3.10	3.20	3.00	3.10	3.20	**	NO
		0 BSC		0.65 B	-	_	50 BS	-	_	50 BS	_		T2055-5	3.15	3.25	3.35	3.15	3.25	3.35	0.40	Y
	0.25	. 1	- 0.25	: T	Γ.	0.25		Ī.	0.25			-	T2855-1	3.15	3.25	3.35	3.15	3.25	3.35	**	NO
		140 0	50 0.45	_	0.65	-	0.55	0.65	0.20	0.40	0.50	-	T2855-2	2.60	2.70	2.80	2.60	2.70	2.80	**	NO
L1	0.00	J.40 0.	30 0.40	-	0.03	0.40	0.00	0.00	0.50	-	0.50	- 1	T2855-3	3.15	3.25	3.35	3.15	3.25	3.35	**	YES
N	- 1	16	<del>-   -</del>	20		H	28	_	-	32	-	- 1-	T2855-4	2.60	2.70	2.80	2.60	2.70	2.80	**	YES
ND.		4	_	5			7			8	-	L	T2855-5	2.60	2.70	2.80	2.60	2.70	2.80	**	NO
NF		4	_	5		_	7		8		L	T2855-6	3.15	3.25	3.35	3.15	3.25	3.35	**	NO	
JEDEC	١٨	/HHB	_	WHH	`	V	VHHD	-1	V	VHHD	2	ŀ	T2855-7	2.60	2.70	2.80	2.60	2.70	2.80	**	YES
JEDEC	**	TITIO	_	*******			*11110	-1		VIIIID	-2	ŀ	T2855-8 T2855N-1	3.15	3.25	3.35	3.15	3.25	3.35	0.40	Y N
TES:												ŀ	T3255-2	3.00	3.10	3.20	3.00	3.10	3.20	**	NO.
. DIMENSI	IONING	& TOLE	RANCIN	G CONF	ORM 1	O ASM	E Y14.	5M-199	94.			ŀ	T3255-3	3.00	3.10	3.20	3.00	3.10	3.20	**	YES
2. ALL DIM	ENSIO	NS ARE	IN MILLI	METERS	. ANG	LES AR	E IN D	EGREE	S.			ı	T3255-4	3.00	3.10	3.20	3.00	3.10	3.20	**	NO
3. N IS THE	E TOTA	L NUME	ER OF T	ERMINA	LS.							ı	T3255N-1	3.00	3.10	3.20	3.00	3.10	3.20	**	NO
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### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



			CC	NOMMC	DIMENS	IONS				
PKG.		36L 6x6	ı		40L 6x6		48L 6x6			
SYMBOL	MIN. NOM. MAX.			MIN.	NOM.	WAX.	MIN.	NOM.	I	
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	Γ	
A1	0	0.02	0.05	0	0.02	0.05	٥	-	Γ	
A2		0.20 REF			0.20 REF	0.20 REF.				
ь	0.20	0.25	D.3D	0.20	0.25	0.30	0.15	0.20	Γ	
D	5.90	6.00	6.10	5.90	6.00	6.10	5.90	6.00	Г	
E	5.90	6.DD	6.10	5.90	6.00	6.10	5.90	5.00	Γ	
e		0.50 BSC			0.50 BSC	0.40 BSC.				
k	0.25	-	_	0.25	-	-	0.25	0.35	Γ	
L	0.45	0.55	D.65	0.30	0.40	0.50	0,40	0.50	Γ	
L1	-	-	-	-	-	-	0.30	0.40	Γ	
N		36			40	48				
ND		9			10	12				
NE		9			10	12				
JEDEC		WJJD-1			WJJD-2	-				

	EXPOSED PAD VARIATIONS												
PKG.		D2			E2	BONDS							
CODES	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.							
T3666-1	3,60	3.70	3.80	3,60	3.70	3.80	NO						
T3666-2	3.60	3,70	3.80	3,60	3,70	3.80	YES						
T3666-3	3.60	3.70	3.80	3.60	3.70	3,80	NO						
T4066-1	4.00	4.10	4.20	4.00	4.10	4.20	NO						
T4066-2	4.00	4.10	4.20	4.00	4.10	4.20	YES						
T4066-3	4.00	4.10	4.20	4.00	4.10	4.20	YES						
T4066-4	4.00	4,10	4.20	4.00	4,10	4.20	NO						
T4066-5	4.00	4.10	4.20	4.00	4.10	4.20	NO						
T4866-1	4.20	4.30	4.40	4.20	4.30	4.40	YES						

#### NOTES:

- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.

ATHE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.

ADIMENSION & APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP.

- 6. ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- 7. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.

⚠ COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS

- 9. DRAWING CONFORMS TO JEDEC MO220, EXCEPT FOR 0.4mm LEAD PITCH PACKAGE T4866-1
- 10. WARPAGE SHALL NOT EXCEED 0.10 mm.



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